

JAWAHARLAL NEHRU TECHNOLOGICAL UNIVERSITY ANANTAPUR

Draft Academic Regulations of M.Tech. (Full Time/Regular) Programme (Effective for the students admitted into I year from the Academic Year 2021-22 and onwards)

Jawaharlal Nehru Technological University Anantapur (JNTUA) offers **Two** Years (**Four** Semesters) full-time Master of Technology (M.Tech.) Degree programme, under Choice Based Credit System (CBCS) in different branches of Engineering and Technology with different specializations.

The Jawaharlal Nehru Technological University Anantapur shall confer M. Tech. degree on candidates who are admitted to the programme and fulfill all the requirements for the award of the degree.

1. Award of the M.Tech. Degree

A student will be declared eligible for the award of the M.Tech. degree if he/she fulfils the following:

- 1.1 Pursues a course of study for not less than two academic years and not more than four academic years.
- 1.2 Registers for 70 credits and secures all 70 credits.
- 2. Students, who fail to fulfil all the academic requirements for the award of the degree within four academic years from the year of their admission, shall forfeit their seat in M.Tech, course and their admission stands cancelled.

3. **Programme of Study:**

The following M.Tech. Specializations are offered at present in different branches of Engineering and Technology in non-autonomous affiliated colleges:

S.No.	Discipline	Name of the Specialization	Code
01	Civil Engineering	Structural Engineering	20
		Geotechnical Engineering	12
		Computer Aided Structural Engineering	35
		Construction Planning & Management	21
		Structural Engineering & Construction Management	91
		Highway Engineering	93
02	Electrical and Electronics	Electrical Power Systems	07
	Engineering	Power Electronics	43
		Power Electronics & Electrical Drives	54
		Power Systems	82
03	Mechanical Engineering	CAD / CAM	04
		Machine Design	15
		Thermal Science & Energy Systems	11
	Refrigeration & Air- Conditioning		17
		Advanced Manufacturing Systems	87



		Thermal Engineering	88
		Production Engineering & Engineering Design	90
		Production Engineering	94
04	Electronics and	Digital Electronics & Communication Systems	38
	Communication	Electronics & Communication Engineering	70
	Engineering	Digital Systems & Computer Electronics	06
		Embedded Systems	55
		VLSI Design	
		VLSI System Design	57
		VLSI	
		VLSI & Embedded Systems	68
		Embedded Systems & VLSI	
		VLSI and Embedded Systems Design	85
05	Computer Science and	Computer Science & Engineering	58
	Engineering	Software Engineering	25
		Computer Networks	08
		Artificial Intelligence & Machine Learning	98

and any other specializations as approved by AICTE/University from time to time.

4. Eligibility for Admissions:

- 4.1 Admission to the M. Tech Program shall be made subject to the eligibility, qualification and specialization prescribed by the A.P. State Government/University from time to time.
- 4.2 Admissions shall be made either on the basis of either the merit rank or Percentile obtained by the qualified student in the relevant qualifying GATE Examination/ the merit rank obtained by the qualified student in an entrance test conducted by A.P. State Government (APPGECET) for M.Tech. programmes/an entrance test conducted by University/on the basis of any other exams approved by the University, subject to reservations as laid down by the Govt. from time to time.

5. Programme related terms:

5.1 *Credit:* A unit by which the course work is measured. It determines the number of hours of instructions required per week. One credit is equivalent to one hour of teaching (Lecture/Tutorial) or two hours of practical work/field work per week.

Credit definition:

1 Hr. Lecture (L) per week	1 credit
1 Hr. Tutorial (T) per week	1 credit
1 Hr. Practical (P) per week	0.5 credit

- 5.2 **Academic Year:** Two consecutive (one odd + one even) semesters constitute one academic year.
- 5.3 *Choice Based Credit System (CBCS):* The CBCS provides choice for students to select from the prescribed courses.



6. Programme Pattern:

- 6.1 Total duration of the of M.Tech. programme is two academic years
- 6.2 Each academic year of study is divided into two semesters.
- 6.3 Each Semester shall be of 22 weeks duration (inclusive of Examinations), with a minimum of 90 instructional days per semester.
- 6.4 The student shall not take more than four academic years to fulfill all the academic requirements for the award of M.Tech. degree from the date of commencement of first year first semester, failing which the student shall forfeit the seat in M.Tech. programme.
- 6.5 The medium of instruction of the programme (including examinations and project reports) will be in English only.
- 6.6 All subjects/courses offered for the M.Tech. degree programme are broadly classified as follows:

S.No.	Broad Course Classification	Course Category	Description			
1.	Core Courses	Foundational & Professional Core Courses (PC)	Includes subjects related to the parent discipline/department/branch of Engineering			
		Professional Elective Courses (PE)	Includes elective subjects related to the parent discipline/department/ branch of Engineering			
2.	Elective Courses	Open Elective Elective subjects which include inter-disciplin subjects or subjects in an area outside the participation discipline which are of importance in the composition of special skill development				
		Research methodology & IPR	To understand importance and process of creation of patents through research			
3.	Research	Technical Seminar	Ensures preparedness of students to undertake major projects/Dissertation, based on core contents related to specialization			
		Cocurricular Activities Dissertation	Attending conferences, scientific presentations and other scholarly activities M.Tech. Project or Major Project			
4.	Audit Courses	Mandatory noncredit courses	Covering subjects of developing desired attitu			

- 6.7 The college shall take measures to implement Virtual Labs (https://www.vlab.co.in) which provide remote access to labs in various disciplines of Engineering and will help student in learning basic and advanced concept through remote experimentation. Student shall be made to work on virtual lab experiments during the regular labs.
- 6.8 A faculty advisor/mentor shall be assigned to each specialization to advise students on the programme, its Course Structure and Curriculum, Choice of Courses, based on his competence, progress, pre-requisites and interest.
- 6.9 Preferably 25% course work for the theory courses in every semester shall be conducted in the blended mode of learning.



7. Attendance Requirements:

- 7.1 A student shall be eligible to appear for the University external examinations if he/she acquires i) a minimum of 50% attendance in each course and ii) 75% of attendance in aggregate of all the courses.
- 7.2 Condonation of shortage of attendance in aggregate up to 10% (65% and above and below 75%) in each semester may be granted by the College Academic Committee.
- 7.3 Condonation of shortage of attendance shall be granted only on genuine and valid reasons on representation by the candidate with supporting evidence
- 7.4 Students whose shortage of attendance is not condoned in any semester are not eligible to take their end examination of that class.
- 7.5 A stipulated fee shall be payable towards condonation of shortage of attendance.
- 7.6 A student will not be promoted to the next semester unless he satisfies the attendance requirements of the present semester. They may seek re-admission into that semester when offered next.
- 7.7 If any candidate fulfils the attendance requirement in the present semester, he shall not be eligible for readmission into the same class.
- 7.8 If the learning is carried out in blended mode (both offline & online), then the total attendance of the student shall be calculated considering the offline and online attendance of the student.

8. Evaluation – Distribution and Weightage of Marks:

The performance of a student in each semester shall be evaluated subject - wise (irrespective of credits assigned), for a maximum of 100 marks for theory and 100 marks for practical, based on Internal Evaluation and End Semester Examination.

- 8.1 There shall be five units in each of the theory subjects. For the theory subjects 60 marks will be for the End Examination and 40 marks will be for Internal Evaluation.
- 8.2 Two Internal Examinations shall be conducted for 30 marks each, one in the middle of the Semester and the other immediately after the completion of instruction. First mid examination shall be conducted for I & II units of the syllabus and second mid examination for III, IV & V units. Each mid exam shall be conducted for a total duration of 120 minutes with 3 questions (without choice) each question for 10 marks. Final Internal marks for a total of 30 marks shall be arrived at by considering the marks secured by the student in both the internal examinations with 80% weightage to the better internal exam and 20% to the other. There shall be an online examination (TWO) conducted during the respective mid examinations by the college for the remaining 10 marks with 20 objective questions.



- 8.3 The following pattern shall be followed in the End Examination:
 - i. Five questions shall be set from each of the five units with either/or type for 12 marks each.
 - ii. All the questions have to be answered compulsorily.
 - iii. Each question may consist of one, two or more bits.
- 8.4 For practical subjects, 60 marks shall be for the End Semester Examinations and 40 marks will be for internal evaluation based on the day-to-day performance.

The internal evaluation based on the day-to-day work-10 marks, record- 10 marks and the remaining 20 marks to be awarded by conducting an internal laboratory test. The end examination shall be conducted by the examiners, with a breakup mark of Procedure-10, Experimentation-25, Results-10, Vivavoce-15.

- 8.5 There shall be a **Technical Seminar** during I year II semester for internal evaluation of 100 marks. A student under the supervision of a faculty member, shall collect the literature on a topic and critically review the literature and submit it to the department in a report form and shall make an oral presentation before the Project Review Committee consisting of Head of the Department, supervisor/mentor and two other faculty members of the department. The student has to secure a minimum of 50% of marks, to be declared successful. If he fails to obtain the minimum marks, he has to reappear for the same as and when supplementary examinations are conducted. The Technical seminar shall be conducted anytime during the semester as per the convenience of the Project Review Committee and students. There shall be no external examination for Technical Seminar.
 - 8.6 There shall be Mandatory **Audit courses** in I & II semesters for zero credits. There is no external examination for audit courses. However, attendance shall be considered while calculating aggregate attendance and student shall be declared to have passed the mandatory course only when he/she secures 50% or more in the internal examinations. In case, the student fails, a reexamination shall be conducted for failed candidates for 40 marks every six months/semester satisfying the conditions mentioned in item 1 & 2 of the regulations.
- 8.7 A candidate shall be deemed to have secured the minimum academic requirement in a subject if he secures a minimum of 40% of marks in the End Examination and a minimum aggregate of 50% of the total marks in the End Semester Examination and Internal Evaluation taken together.
- 8.8 In case the candidate does not secure the minimum academic requirement in any of the subjects he/she has to reappear for the Semester Examination either supplementary or regular in that subject or repeat the course when next offered or do any other specified subject as may be required.



8.9 The laboratory records and mid semester test papers shall be preserved for a minimum of 3 years in the respective institutions as per the University norms and shall be produced to the Committees of the University as and when the same are asked for.

9. Credit Transfer Policy

As per University Grants Commission (Credit Framework for Online Learning Courses through SWAYAM) Regulation, 2016, the University shall allow up to a maximum of 40% of the total courses being offered in a particular Programme in a semester through the Online Learning courses through SWAYAM.

- 9.1 The University shall offer credit mobility for MOOCs and give the equivalent credit weightage to the students for the credits earned through online learning courses through SWAYAM platform.
- 9.2 The online learning courses available on the SWAYAM platform will be considered for credit transfer. SWAYAM course credits are as specified in the platform
- 9.3 Student registration for the MOOCs shall be only through the institution, it is mandatory for the student to share necessary information with the institution
- 9.4 The institution shall select the courses to be permitted for credit transfer through SWAYAM. However, while selecting courses in the online platform institution would essentially avoid the courses offered through the curriculum in the offline mode.
- 9.5 The institution shall notify at the beginning of semester the list of the online learning courses eligible for credit transfer in the forthcoming Semester.
- 9.6 The institution shall also ensure that the student has to complete the course and produce the course completion certificate as per the academic schedule given for the regular courses in that semester
- 9.7 The institution shall designate a faculty member as a Mentor for each course to guide the students from registration till completion of the credit course.
- 9.8 The university shall ensure no overlap of SWAYAM MOOC exams with that of the university examination schedule. In case of delay in SWAYAM results, the university will re-issue the marks sheet for such students.
- 9.9 Student pursuing courses under MOOCs shall acquire the required credits only after successful completion of the course and submitting a certificate issued by the competent authority along with the percentage of marks and grades.
- 9.10 The institution shall submit the following to the examination section of the university:
 - a) List of students who have passed MOOC courses in the current semester along with the certificates of completion.
 - b) Undertaking form filled by the students for credit transfer.
- 9.11 The university shall resolve any issues that may arise in the implementation of this policy from time to time and shall review its credit transfer policy in the



light of periodic changes brought by UGC, SWAYAM, NPTEL and state government.

Note: Students shall also be permitted to register for MOOCs offered through online platforms other than SWAYAM NPTEL. In such cases, credit transfer shall be permitted only after seeking approval of the University at least three months prior to the commencement of the semester.

10. Re-registration for Improvement of Internal Evaluation Marks:

A candidate shall be given one chance to re-register for each subject provided the internal marks secured by a candidate are less than 50% and has failed in the end examination

- 10.1 The candidate should have completed the course work and obtained examinations results for **I, II and III** semesters.
- 10.2 The candidate should have passed all the subjects for which the Internal Evaluation marks secured are more than 50%.
- 10.3 Out of the subjects the candidate has failed in the examination due to Internal Evaluation marks secured being less than 50%, the candidate shall be given one chance for each Theory subject and for a maximum of **three** Theory subjects for Improvement of Internal evaluation marks.
- 10.4 The candidate has to re-register for the chosen subjects and fulfill the academic requirements.
- 10.5 For reregistration the candidates have to apply to the University through the college by paying the requisite fees and get approval from the University before the start of the semester in which re-registration is required
- 10.6 In the event of availing the Improvement of Internal evaluation marks, the internal evaluation marks as well as the End Examinations marks secured in the previous attempt(s) for the reregistered subjects stand cancelled.

11. Evaluation of Project/Dissertation Work:

The Project work shall be initiated at the beginning of the III Semester and the duration of the Project is of two semesters. Evaluation of Project work is for 300 marks with 200 marks for internal evaluation and 100 marks for external evaluation. Internal evaluation of the Project Work – I & Project work – II in III & IV semesters respectively shall be for 100 marks each. External evaluation of final Project work viva voce in IV semester shall be for 100 marks.

A Project Review Committee (PRC) shall be constituted with the Head of the Department as Chairperson, Project Supervisor and one faculty member of the department offering the M.Tech. programme.



- 11.1 A candidate is permitted to register for the Project Work in III Semester after satisfying the attendance requirement in all the subjects, both theory and laboratory (in I & II semesters).
- 11.2 A candidate is permitted to submit Project dissertation with the approval of PRC. The candidate has to pass all the theory, practical and other courses before submission of the Thesis.
- 11.4 Project work shall be carried out under the supervision of teacher in the parent department concerned.
- 11.5 A candidate shall be permitted to work on the project in an industry/research organization on the recommendation of the Head of the Department. In such cases, one of the teachers from the department concerned would be the internal guide and an expert from the industry/ research organization concerned shall act as co-supervisor/ external guide. It is mandatory for the candidate to make full disclosure of all data/results on which they wish to base their dissertation. They cannot claim confidentiality simply because it would come into conflict with the Industry's or R&D laboratory's own interests. A certificate from the external supervisor is to be included in the dissertation.
- 11.6 Continuous assessment of Project Work I and Project Work II in III & IV semesters respectively will be monitored by the PRC.
- 11.7 The candidate shall submit status report by giving seminars in three different phases (two in III semester and one in IV semester) during the project work period. These seminar reports must be approved by the PRC before submission of the Project Thesis.
- 11.8 After registration, a candidate must present in Project Work Review I, in consultation with his Project Supervisor, the title, objective and plan of action of his Project work to the PRC for approval within four weeks from the commencement of III Semester. Only after obtaining the approval of the PRC can the student initiate the project work.
- 11.9 The Project Work Review II in III semester carries internal marks of 100. Evaluation should be done by the PRC for 50 marks and the Supervisor will evaluate the work for the other 50 marks. The Supervisor and PRC will examine the Problem Definition, Objectives, Scope of Work, Literature Survey in the same domain and progress of the Project Work.
- 11.10 A candidate has to secure a minimum of 50% of marks to be declared successful in Project Work Review II. Only after successful completion of Project Work Review II, candidate shall be permitted for Project Work Review III in IV Semester. The unsuccessful students in Project Work Review II shall reappear for it as and when supplementary examinations are conducted.
- 11.11 The Project Work Review III in IV semester carries 100 internal marks. Evaluation should be done by the PRC for 50 marks and the Supervisor will evaluate it for the other 50 marks. The PRC will examine the overall progress



- of the Project Work and decide whether or not eligible for final submission. A candidate has to secure a minimum of 50% of marks to be declared successful in Project Work Review III. If he fails to obtain the required minimum marks, he has to reappear for Project Work Review III after a month.
- 11.12 For the approval of PRC the candidate shall submit the draft copy of dissertation to the Head of the Department and make an oral presentation before the PRC.
- 11.13 After approval from the PRC, the students are required to submit a report showing that the plagiarism is within 30%. The dissertation report will be accepted only when the plagiarism is within 30%, which shall be submitted along with the dissertation report.
- 11.14 Research paper related to the Project Work shall be published in conference proceedings/UGC recognized journal. A copy of the published research paper shall be attached to the dissertation.
- 11.15 After successful plagiarism check and publication of research paper, three copies of the dissertation certified by the supervisor and HOD shall be submitted to the College.
- 11.16 The dissertation shall be adjudicated by an external examiner selected by the University. For this, the Principal of the College shall submit a panel of three examiners as submitted by the supervisor concerned and department head for each student. However, the dissertation will be adjudicated by one examiner nominated by the University.
- 11.17 If the report of the examiner is not satisfactory, the candidate shall revise and resubmit the dissertation, in the time frame as decided by the PRC. If report of the examiner is unfavorable again, the thesis shall be summarily rejected. The candidate has to reregister for the project and complete the project within the stipulated time after taking the approval from the University
- 11.18 If the report of the examiner is satisfactory, the Head of the Department shall coordinate and make arrangements for the conduct of Project Viva voce exam.
- 11.19 The Project Viva voce examinations shall be conducted by a board consisting of the Supervisor, Head of the Department and the external examiner who has adjudicated the dissertation. For Dissertation Evaluation (Viva voce) in IV Sem. there are external marks of 100 and it is evaluated by external examiner. The candidate has to secure a minimum of 50% marks in Viva voce exam.
- 11.20 If he fails to fulfill the requirements as specified, he will reappear for the Project Viva voce examination only after three months. In the reappeared examination also, if he fails to fulfill the requirements, he will not be eligible for the award of the degree.

12. Credits for Co-curricular Activities

The credits assigned for co-curricular activities shall be given by the principals of the colleges and the same shall be submitted to the University.



A Student shall earn 02 credits under the head of co-curricular activities, viz., attending Conference, Scientific Presentations and Other Scholarly Activities.

Following are the guidelines for awarding Credits for Co-curricular Activities

Name of the Activity	Maximum Credits / Activity
Participation in National Level Seminar/ Conference / Workshop	1
/Training programs (related to the specialization of the student)	1
Participation in International Level Seminar / Conference /	2
workshop/Training programs held outside India (related to the	
specialization of the student)	
Academic Award/Research Award from State Level/National	1
Agencies	
Academic Award/Research Award from International Agencies	2
Research / Review Publication in National Journals (Indexed in	1
Scopus / Web of Science)	
Research / Review Publication in International Journals with	2
Editorial board outside India (Indexed in Scopus / Web of	
Science)	

Note:

- i) Credit shall be awarded only for the first author. Certificate of attendance and participation in a Conference/Seminar is to be submitted for awarding credit.
- ii) Certificate of attendance and participation in workshops and training programs (Internal or External) is to be submitted for awarding credit. The total duration should be at least one week.
- iii) Participation in any activity shall be permitted only once for acquiring required credits under cocurricular activities

13. Grading:

As a measure of the student's performance, a 10-point Absolute Grading System using the following Letter Grades and corresponding percentage of marks shall be followed:

After each course is evaluated for 100 marks, the marks obtained in each course will be converted to a corresponding letter grade as given below, depending on the range in which the marks obtained by the student fall.

Structure of Grading of Academic Performance

Range in which the marks	Grade	Grade points
in the subject fall		Assigned
≥ 90	S (Superior)	10
≥ 80 < 90	A (Excellent)	9
≥ 70 < 80	B (Very Good)	8
≥ 60 < 70	C (Good)	7
≥ 50 < 60	D (Pass)	6
< 50	F (Fail)	0
Absent	Ab (Absent)	0



- i) A student obtaining Grade 'F' or Grade 'Ab' in a subject shall be considered failed and will be required to reappear for that subject when it is offered the next supplementary examination.
- ii) For noncredit audit courses, "Satisfactory" or "Unsatisfactory" shall be indicated instead of the letter grade and this will not be counted for the computation of SGPA/CGPA/Percentage.

Computation of Semester Grade Point Average (SGPA) and Cumulative Grade Point Average (CGPA):

The Semester Grade Point Average (SGPA) is the ratio of sum of the product of the number of credits with the grade points scored by a student in all the courses taken by a student and the sum of the number of credits of all the courses undergone by a student, i.e.,

SGPA =
$$\Sigma (C_i \times G_i)/\Sigma C_i$$

where, C_i is the number of credits of the i^{th} subject and G_i is the grade point scored by the student in the i^{th} course.

i) The Cumulative Grade Point Average (CGPA) will be computed in the same manner considering all the courses undergone by a student over all the semesters of a program, i.e.,

$$CGPA = \sum (C_i \times S_i) / \sum C_i$$

where " S_i " is the SGPA of the i^{th} semester and C_i is the total number of credits up to that semester.

- ii) Both SGPA and CGPA shall be rounded off to 2 decimal points and reported in the transcripts.
- iii) While computing the SGPA the subjects in which the student is awarded Zero grade points will also be included.

Grade Point: It is a numerical weight allotted to each letter grade on a 10-point scale. Letter Grade: It is an index of the performance of students in a said course. Grades are denoted by letters S, A, B, C, D and F.

14. Award of Class:

After a student has satisfied the requirements prescribed for the completion of the program and is eligible for the award of M. Tech. Degree, he shall be placed in one of the following three classes:

Class Awarded	Percentage of Marks to be secured
First Class with Distinction	≥70%
First Class	< 70% ≥ 60%
Pass Class	< 60% ≥ 50%



15. **Exit Policy:** The student shall be permitted to exit with a PG Diploma based on his/her request to the university through the respective institution at the end of first year subject to passing all the courses in first year.

The University shall resolve any issues that may arise in the implementation of this policy from time to time and shall review the policy in the light of periodic changes brought by UGC, AICTE and State government.

16. Withholding of Results:

If the candidate has any case of in-discipline pending against him, the result of the candidate shall be withheld, and he will not be allowed/promoted into the next higher semester. The issue of degree is liable to be withheld in such cases.

17. Transitory Regulations

Discontinued, detained, or failed candidates are eligible for readmission as and when the semester is offered after fulfilment of academic regulations. Candidates who have been detained for want of attendance or not fulfilled academic requirements or who have failed after having undergone the course in earlier regulations or have discontinued and wish to continue the course are eligible for admission into the unfinished semester from the date of commencement of class work with the same or equivalent subjects as and when subjects are offered, subject to Section 2 and they will follow the academic regulations into which they are readmitted.

18. General:

- 17.1 The academic regulations should be read as a whole for purpose of any interpretation.
- 17.2 Disciplinary action for Malpractice/improper conduct in examinations is appended.
- 17.3 There shall be no places transfer within the constituent colleges and affiliated colleges of Jawaharlal Nehru Technological University Anantapur.
- 17.4 Where the words "he", "him", "his", occur in the regulations, they include "she", "her", "hers".
- 17.5 In the case of any doubt or ambiguity in the interpretation of the above rules, the decision of the Vice-Chancellor is final.
- 17.6 The University may change or amend the academic regulations or syllabi at any time and the changes or amendments shall be made applicable to all the students on rolls with effect from the dates notified by the University.



RULES FOR

DISCIPLINARY ACTION FOR MALPRACTICES / IMPROPER CONDUCT IN EXAMINATIONS

	Nature of Malpractices/Improper conduct	Punishment
	If the candidate:	
1.(a)	Possesses or keeps accessible in examination hall, any paper, note book, programmable calculators, Cell phones, pager, palm computers or any other form of material concerned with or related to the subject of the examination (theory or practical) in which he is appearing but has not made use of (material shall include any marks on the body of the candidate which can be used as an aid in the subject of the examination)	Expulsion from the examination hall and cancellation of the performance in that subject only.
(b)	Gives assistance or guidance or receives it from any other candidate orally or by any other body language methods or communicates through cell phones with any candidate or persons in or outside the exam hall in respect of any matter.	Expulsion from the examination hall and cancellation of the performance in that subject only of all the candidates involved. In case of an outsider, he will be handed over to the police and a case is registered against him.
2.	Has copied in the examination hall from any paper, book, programmable calculators, palm computers or any other form of material relevant to the subject of the examination (theory or practical) in which the candidate is appearing.	Expulsion from the examination hall and cancellation of the performance in that subject and all other subjects the candidate has already appeared including practical examinations and project work and shall not be permitted to appear for the remaining examinations of the subjects of that semester/year. The Hall Ticket of the candidate is to be cancelled and sent to the University.
3.	Impersonates any other candidate in connection with the examination.	The candidate who has impersonated shall be expelled from examination hall. The candidate is also debarred for four consecutive semesters from class work and all University examinations. The continuation of the course by the candidate is subject to the academic regulations in connection with forfeiture of seat. The performance of the original candidate who has been impersonated, shall be cancelled in all the subjects of the examination (including practicals and project work) already appeared and shall not be allowed to appear for examinations of the remaining subjects of that semester/year. The candidate is also debarred for four consecutive semesters from class work and all University examinations if his involvement is established. Otherwise, the candidate is debarred for two consecutive semesters from class work and all University examinations. The continuation of the course by the candidate is subject to the academic regulations in connection with forfeiture of seat. If the imposter is an outsider, he will be handed over to the police and a case is registered against him.



5.	Smuggles in the Answer book or additional sheet or takes out or arranges to send out the question paper during the examination or answer book or additional sheet, during or after the examination. Uses objectionable, abusive or offensive language in the answer paper or in letters to the examiners or	Expulsion from the examination hall and cancellation of performance in that subject and all the other subjects the candidate has already appeared including practical examinations and project work and shall not be permitted for the remaining examinations of the subjects of that semester/year. The candidate is also debarred for two consecutive semesters from class work and all University examinations. The continuation of the course by the candidate is subject to the academic regulations in connection with forfeiture of seat. Cancellation of the performance in that subject only.
	writes to the examiner requesting him to award pass marks.	
6.	Refuses to obey the orders of the Chief Superintendent /Assistant - Superintendent /any officer on duty or misbehaves or creates disturbance of any kind in and around the examination hall or organizes a walk out or instigates others to walk out, or threatens the officer-in charge or any person on duty in or outside the examination hall of any injury to his person or to any of his relations whether by words, either spoken or written or by signs or by visible representation, assaults the officer-in-charge, or any person on duty in or outside the examination hall or any of his relations, or indulges in any other act of misconduct or mischief which result in damage to or destruction of property in the examination hall or any part of the College campus or engages in any other act which in the opinion of the officer on duty amounts to use of unfair means or misconduct or has the tendency to disrupt the orderly conduct of the examination.	In case of students of the college, they shall be expelled from examination halls and cancellation of their performance in that subject and all other subjects the candidate(s) has (have) already appeared and shall not be permitted to appear for the remaining examinations of the subjects of that semester/year. If the candidate physically assaults the invigilator/officer-in-charge of the Examinations, then the candidate is also debarred and forfeits his/her seat. In case of outsiders, they will be handed over to the police and a police case is registered against them.
7.	Leaves the exam hall taking away answer script or intentionally tears of the script or any part thereof inside or outside the examination hall.	Expulsion from the examination hall and cancellation of performance in that subject and all the other subjects the candidate has already appeared including practical examinations and project work and shall not be permitted for the remaining examinations of the subjects of that semester/year. The candidate is also debarred for two consecutive semesters from class work and all University examinations. The continuation of the course by the candidate is subject to the academic regulations in connection with forfeiture of seat.
8.	Possess any lethal weapon or firearm in the examination hall.	Expulsion from the examination hall and cancellation of the performance in that subject and all other subjects the candidate has already appeared including practical examinations and project work and shall not be permitted for the remaining examinations of the subjects of that semester/year. The candidate is also debarred and forfeits the seat.
9.	If student of the college, who is not a candidate for the particular examination or any person not connected with the college indulges in any malpractice or improper conduct mentioned in clause 6 to 8.	Student of the colleges expulsion from the examination hall and cancellation of the performance in that subject and all other subjects the candidate has already appeared including practical examinations and project



		work and shall not be permitted for the remaining examinations of the subjects of that semester/year. The candidate is also debarred and forfeits the seat. Person (s) who do not belong to the College will be handed over to police and, a police case will be registered against them.
10.	Comes in a drunken condition to the examination hall.	Expulsion from the examination hall and cancellation of the performance in that subject and all other subjects the candidate has already appeared including practical examinations and project work and shall not be permitted for the remaining examinations of the subjects of that semester/year.
11.	Copying detected on the basis of internal evidence, such as, during valuation or during special scrutiny.	Cancellation of the performance in that subject only or in that subject and all other subjects the candidate has appeared including practical examinations and project work of that semester / year examinations, depending on the recommendation of the committee.
12.	If any malpractice is detected which is not covered in the above clauses 1 to 11 shall be reported to the University for further action to award suitable punishment.	

- 1. Malpractices identified by squad or special invigilators
- 2. Punishments to the candidates as per the above guidelines.
- 3. Punishment for institutions: (if the squad reports that the college is also involved in encouraging malpractices)
- 4. A show cause notice shall be issued to the college.
- 5. Impose a suitable fine on the college.
- 6. Shifting the examination center from the college to another college for a specific period of not less than one year.

Note:

Whenever the performance of a student is cancelled in any subject/subjects due to Malpractice, he has to register for End Examinations in that subject/subjects consequently and has to fulfil all the norms required for the award of Degree.



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

COMMON COURSE STRUCTURE & SYLLABI

SEMESTER – I

S. No.	Course	Course Name	Category	Hour	Hours per week		Credits
	codes			L	T	P	
1.	21D57101	CMOS Analog IC Design	PC	3	0	0	3
2.	21D57102	CMOS Digital IC Design	PC	3	0	0	3
3.	21D57103a 21D57103b 21D57103c	Program Elective – 1 Microchip Fabrication Techniques Nanomaterials and Nanotechnology CAD for VLSI	PE	3	0	0	3
4.	21D57104a 21D57104b 21D57104c	Program Elective – 1 Device Modelling FPGA Architectures and Applications ASIC Design	PE	3	0	0	3
5.	21D57105	CMOS Analog IC Design Lab	PC	0	0	4	2
6.	21D57106	CMOS Digital IC Design Lab	PC	0	0	4	2
7.	21DRM101	Research Methodology and IPR	MC	2	0	0	2
8.	21DAC101a 21DAC101b 21DAC101c	Audit Course – I English for Research paper writing Disaster Management Sanskrit for Technical Knowledge	AC	2	0	0	0
Total						18	



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COMMON COURSE STRUCTURE & SYLLABI

SEMESTER – II

S.No.	Course	Course Name	Category	Hou	Hours per week		Credit
	codes			L	T	P	S
1.	21D57201	CMOS Mixed Signal IC Design	PC	3	0	0	3
2.	21D57202	Physical Design Automation	PC	3	0	0	3
3.	21D57203a 21D57203b 21D57203c	Program Elective – III SoC Testing and Verification Semiconductor Memory Design and Testing MEMS System Design	PE	3	0	0	3
4.	21D57204a 21D57204b 21D57204c	Program Elective – IV Low Power VLSI Design IoT and its Applications VLSI Signal Processing	PE	3	0	0	3
5.	21D57205	CMOS Mixed Signal IC Design Lab	PC	0	0	4	2
6.	21D57206	Physical Design Automation Lab	PC	0	0	4	2
7.	21D57207	Technical seminar	PR	0	0	4	2
8.	21DAC201a 21DAC201b 21DAC201c	Audit Course – II Pedagogy Studies Stress Management for Yoga Personality Development through Life Enlightenment Skills	AC	2	0	0	0
		Total					18



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COMMON COURSE STRUCTURE & SYLLABI

SEMSTER - III

S.No.	Course	Course Name	Categor	Hou	Hours per		Credi	
	codes		\mathbf{y}	L	T	P	ts	
1.	21D57301a 21D57301b 21D06203a	Program Elective – V Bi-CMOS Technology and Applications Optimization Techniques and Applications in VLSI Design SoC Architecture	PE	3	0	0	3	
2.	21DOE301b 21DOE301c 21DOE301e	Open Elective Industrial Safety Business Analytics Waste to Energy	OE	3	0	0	3	
3.	21D57302	Dissertation Phase – I	PR	0	0	20	10	
4.	21D57303	Co-curricular Activities					2	
	Total							

SEMESTER - IV

S.No.	Course	Course Name	Category	Hours per		Hours per		Hours per	
	codes			L	T	P			
1.	21D57401	Dissertation Phase – II	PR	0	0	32	16		
		Total					16		



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COMMON COURSE STRUCTURE & SYLLABI

~ ~ ~				1	T ~
Course Code	CMOS ANALOG IC DESIGN	L	<u>T</u>	P	C
21D57101	0 4	3	0	0	3
	Semester			I	
Course Objectiv	001				
	rse focuses on theory, analysis and design of analog integrated	ciro	mite	in h	oth
	nd Metal-Oxide-Silicon (MOS) technologies.	CII	zuits	III C	oui
•	ign concepts, issues and tradeoffs involved in analog IC design are	evn	orec	1	
	understanding and real-life applications are emphasized throughout				
	about Design of CMOS Op Amps, Compensation of Op Amps,				WO.
	Amps, Power Supply Rejection Ratio of Two-Stage Op Amps, Ca				
	ment Techniques of OP Amp.	iscai		рΑп	ıps
	about Characterization of Comparator, Two-Stage, Open-Loc	on (٦ _{om}	narat	ore
	g the Performance of Open-Loop Comparators, Discrete-Time Com	•		•	OIS
	es (CO): Student will be able to	ipui	atori	occ.	
	OSFET based analog integrated circuits.				
-	nalog circuits at least to the first order.				
•	e the trade-offs involved in analog integrated circuit design.				
* *	d and appreciate the importance of noise and distortion in analog ci	rcui	te		
	complex engineering problems critically in the domain of analogous			cian	fo
•	g research.	gı	o uc	sign	10
	ineering problems for feasible and optimal solutions in the core area	a			
UNIT - I	lineering problems for reastore and optimal solutions in the core are		rture	Hrs:	
	vice Physics: General Considerations, MOS I/V Characteristics				
	vice models and MOS Capacitor. Short Channel Effects and Device				
	 Basic Concepts, Common Source Stage, Source Follower, Com 				
Cascode Stage.					.6
UNIT - II		Leo	cture	Hrs:	
Differential Am	plifiers: Single Ended and Differential Operation, Basic Differential	al Pa	air, (Comn	nor
Mode Response.	Differential Pair with MOS loads, Gilbert Cell. Passive and	d A	ctive	Cur	ren
Mirrors – Basic (Current Mirrors, Cascode Current Mirrors, Active Current Mirrors.	Cur	rent	Steer	ing
Circuit					
UNIT - III		Le	cture	Hrs:	
	ponse of Amplifiers:General Considerations, Common Source		_		
· ·	mon Gate Stage, Cascode Stage, Differential Pair. Noise – T				ise
•	Noise in circuits, Noise in single stage amplifiers, Noise in Differe				
UNIT - IV				Hrs:	
-	fiers: General Considerations, Feedback Topologies, Effect of Load	_	•		
	eneral Considerations, One Stage Op Amps, Two Stage Op Amps,				
	de Feedback, Input Range limitations, Slew Rate, Power S	upp	ly R	ejecti	ion
	s, Stability and Frequency Compensation.	_		**	
UNIT - V				Hrs:	
	naracterization of comparator, Two-Stage, Open-Loop comparator				
Loop Comparate	ors, Improving the Performance of Open-Loop Comparators	, L	uscr	ete-T	ım

Comparators. **Textbooks:**

- 1. B.Razavi, "Design of Analog CMOS Integrated Circuits", 2ndEdition, McGraw Hill Edition2016.
- 2. Paul.R.Gray& Robert G. Meyer, "Analysis and Design of Analog Integrated Circuits", Wiley,



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COMMON COURSE STRUCTURE & SYLLABI

5thEdition, 2009.

- 1.T.C.Carusone, D.A.Johns&K.Martin, "Analog Integrated Circuit Design", 2ndEdition, Wiley, 2012.
- 2. P.E.Allen&D.R.Holberg, "CMOS Analog Circuit Design", 3rd Edition, Oxford University Press, 2011
- 3. R.Jacob Baker, "CMOS Circuit Design, Layout, and Simulation", 3rd Edition, Wiley, 2010.
- 4. Adel S. Sedra, Kenneth C. Smith, Arun, "Microelectronic Circuits", 6th Edition, Oxford University Press



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COMMON COURSE STRUCTURE & SYLLABI

Course Code CMOS DIGITAL IC DESIGN	L	T	P	C
21D57102	3	0	0	3
Semester			Ī	
Course Objectives:			TO CIT	
• To understand the fundamental properties of digital Integrated circuits us				
equations and to develop skills for various logic circuits using CMOS rela	ted de	sign s	styles	٠.
The course also involves analysis of performance metrics. The course also involves analysis of performance metrics. The course also involves analysis of performance metrics.				0
To teach fundamentals of CMOS Digital integrated circuit design suc			tance	of
Pseudo logic, Combinational MOS logic circuits and Sequential MOS log				
 To teach the fundamentals of Dynamic logic circuits and basic semic 			emo	ries
which are the basics for the design of high performance digital integrated	circuit	s.		
Course Outcomes (CO): Student will be able to				
 Demonstrate advanced knowledge in Static and dynamic characteristics of 	CMO	S,		
 Estimate Delay and Power of Adders circuits. 				
 Classify different semiconductor memories. 				
 Analyze, design and implement combinational and sequential MOS logic of 	ircuits	١.		
• Analyze complex engineering problems critically in the domain of di	gital I	C de	sign	for
conducting research.			Ü	
• Solve engineering problems for feasible and optimal solutions in the core a	rea of	digit	al IC	s
UNIT - I		cture		
MOS Design Pseudo NMOS Logic:Inverter, Inverter threshold voltage, Output l	igh vo	ltage	,	
Output Low voltage, Gain at gate threshold voltage, Transient response, Rise time	, Fall	ime,	Pseu	do
NMOS logic gates, Transistor equivalency, CMOS Inverter logic.				
UNIT - II	Le	cture	Hrs:	
Combinational MOS Logic Circuits: MOS logic circuits with NMOS loads, Pri	mitive	CMO	OS lo	gic
gates-NOR & NAND gate, Complex Logic circuits design-Realizing Boolean	expr	essio	ns us	ing
NMOS gates and CMOS gates, AOI and OIA gates, CMOS full adder, CMOS	transr	nissic	n ga	tes,
Designing with Transmission gates.				
UNIT - III	Le	cture	Hrs:	
Sequential MOS Logic Circuits: Behavior of bistable elements, SR Latch, Clo	cked	atch	and	flip
flop circuits, CMOS D latch and edge triggered flip-flop				
UNIT - IV	Le	cture	Hrs:	
Dynamic Logic Circuits: Basic principle, Voltage Bootstrapping, Synchron	ous d	ynan	nic p	ass
transistor circuits, Dynamic CMOS transmission gate logic, High performance	e Dyn	amic	CM	OS
circuits.				
UNIT - V	Le	cture	Hrs:	
Semiconductor Memories: Types, RAM array organization, DRAM – Types,	Operat	ion,	Leak	age
currents in DRAM cell and refresh operation, SRAM operation Leakage curre	nts in	SRA	М се	ells,

Textbooks:

Flash Memory-NOR flash and NAND flash.

- 1. Neil Weste, David Harris, "CMOS VLSI Design: A Circuits and Systems Perspective", 4th Edition, Pearson, 2010
- 2. Digital Integrated Circuit Design Ken Martin, Oxford University Press, 2011.
- 3. CMOS Digital Integrated Circuits Analysis and Design Sung-Mo Kang, Yusuf Leblebici, TMH, 3rd Edition, 2011.



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COMMON COURSE STRUCTURE & SYLLABI

- Introduction to VLSI Systems: A Logic, Circuit and System Perspective Ming-BO Lin, CRC Press, 2011
- 2. Digital Integrated Circuits A Design Perspective, Jan M.Rabaey, AnanthaChandrakasan, Borivoje Nikolic, 2ndEdition, PHI.



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COMMON COURSE STRUCTURE & SYLLABI

Course Code	MICROCHIP FABRICATION TECHNIQUES	L	T	P	C
21D57103a		3	0	0	3
	Semester			[
Course Objectiv	es:				
 Compreh 	end impact of semiconductor industry on the design of developm	ent	of in	tegra	ted
circuits.					
 Acquaint 	with clean room technology				
 Understa 	nd oxidation methods, aspects of photolithography, diffusion,	ion	impl	antat	ion
technique	es.				
 Specify 	NMOS and CMOS design rules corresponding to 180r	ım,	90n	m a	and
45nm tec	hnologies				
 Understa 	nd packaging principles				
Course Outcome	es (CO): Student will be able to				
 Understar 	d various stages of fabrication				
 Understar 	d Various packaging techniques and Design rules.				
 Classify v 	arious thin films and its characteristics.				
UNIT - I		Lec	cture	Hrs:	
	Processing: Overview of semiconductor industry, Stages of Manuf				
and product tr	ends, Crystal growth, Basic wafer fabrication operations,	pro	cess	yiel	ds,
Semiconductor	naterial preparation, Yield measurement, Contamination sourc	es,	Clea	n ro	om
construction.					
UNIT - II				Hrs:	
	y:Oxidation and Photolithography, Ten step patterning proce				
	es of photoresists, Storage and control of photoresists, photo maski	ng p	roce	ss, H	ard
	pect, Dry etching Wet etching, resist stripping.	· ·		**	
UNIT - III	T 1 (4) D ' 11 '4' D'6' '			Hrs:	
	Implantation: Doping and depositions: Diffusion process steps, d	epos	sition	, Dri	ve-
UNIT - IV	implantation-1, Ion implantation-2.	La		Hrs:	
	s and Growth: Metallization, CVD basics, CVD process steps, Lo				(ID
	enhanced CVD systems, Vapour phase epitaxy, molecular beam epi			ie C	۷D
UNIT - V	minanced CVD systems, Vapour phase epitaxy, morecular beam epi			Hrs:	
	ules and Scaling, BICMOS ICs: Choice of transistor types,				ors
Resistors, capaci	•		ши	iisist	,
	characteristics, package functions, package operations.				
Textbooks:	Time weeks to the state of the				
	, Microchip fabrication, McGraw Hill, 1997.				
	Deal, M.D. and Griffin, P.B., "Silicon VLSI Technology: Fundamental Company of the Company of th	enta	ls,		
	odeling", 3rd Ed., Prentice-Hall, 2000.				
Reference Book	3				
1. C.Y. Chang an	d S.M. Sze, ULSI technology, McGraw Hill, 2000				
•	LSI Fabrication principles, John Wiley and Sons, NY, 1994				
	I technology, McGraw-Hill Book company, NY, 1988				



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COMMON COURSE STRUCTURE & SYLLABI

Course Code	NANOMATERIALS AND NANOTECHNOLOGY	L	T	P	C
21D57103b		3	0	0	3
	Semester]	[
Course Objectiv	res:				
To unders	tand the basic idea behind the design and fabrication of nano scale s	syste	ms.		
 To unders 	stand and frmulate new engineering solutions for current problems	and	tech	nolog	gies
for future	applications.				
 To acquir 	e knowledge on the operation of fabrication and characterization de	evic	es to	achi	eve
precisely	designed systems.				
Course Outcom	es (CO): Student will be able to				
 Understar 	nd the basic science behind the design and fabrication of nano scale	syste	ems.		
 Understar 	nd and formulate new engineering solutions for current problems	an	d co	mpet	ing
	ies for future applications.				
	er disciplinary projects applicable to wide areas by clearing	and	l fix	ing	the
	s in system development.				
	etailed knowledge of the operation of fabrication and characterize	atio	n de	vices	to
	recisely designed systems.				
UNIT - I			cture		
	nano materials and nanotechnologies, Features of nanostructures,				
	nd technologies. Nano dimensional Materials 0D, 1D, 2D structures				
	ace Atoms – Specific Surface Energy and Surface Stress – Effect				
	onon Density of States – the General Methods available for the president of the president o				
	- precipitate – reactive– hydrothermal/solvo thermal methods – su ng – potential Uses.	шао	iiity	OI S	uCII
UNIT - II	ng potential eses.	Lea	ture	Hrs:	
	nanomaterials, Classification, Zero-dimensional nanomaterials,				
	wo-dimensional nano materials, three dimensional nanomaterials.L				
	nd its Applications, Synthesis, Properties and applications of L				
Carbon-Related I					
UNIT - III		Lec	ture	Hrs:	
Micro- and Nan	olithography Techniques, Emerging Applications, Introduction t	o N	licro	elec	ctro
	ems (MEMS), Advantages and Challenges of MEMS, Fabrication				
Surface Microma	chining, Bulk Micromachining, Molding. Introduction to Nano Pho				
UNIT - IV			cture		
	enthesis of CNTs - Arc-discharge, Laser-ablation, Catalytic				
	CNT"s - Multi-walled nanotubes, Single-walled nano tubes Option				
CNT"s, Electric	al transport in perfect nanotubes, Applications as case studies	. Sy	ınthe	sis a	and

Lecture Hrs:

Ferroelectric materials, coating, molecular electronics and Nano electronics, biological and environmental, membrane based application, polymer based application.

Textbooks:

UNIT - V

Applications of CNTs.

- 1. Kenneth J.Klabunde and Ryan M.Richards, "Nanoscale Materials in Chemistry", 2ndedition, John Wiley and Sons, 2009.
- 2. I Gusev and A Rempel, "Nanocrystalline Materials", Cambridge International Science Publishing, 1stIndian edition by Viva Books Pvt. Ltd. 2008.



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COMMON COURSE STRUCTURE & SYLLABI

3. B.S.Murty,P.Shankar,Baldev Raj, B.B.Rath, James Murday, "Nanoscience and Nanotechnology", Tata McGrawHill Education 2012.

- 1. Digital Integrated Circuit Design Ken Martin, Oxford University Press, 2011.
- 2. Digital Integrated Circuits A Design Perspective, Jan M.Rabaey, AnantChandrakasan, Borvivoje Nikolic, 2nd Edition, PHI.



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COMMON COURSE STRUCTURE & SYLLABI

Course Code	CAD FOR VLSI	L	T	P	С
21D57103c	CID TOR VEST	3	0	0	3
212071000	Semester]		
Course Objectiv					
	tand the various phases of CAD for digital electronic systems, t	from	digi	tal lo	gic
I .	n to physical design, including test and verification.				
	nstrate knowledge and understanding of fundamental concepts	in (CAD	and	to
	capability for CAD tool development and enhancement.				
_	te the application of fundamentals of VLSI technologies				
_	ize the implemented design for area, timing and power by a	ιpply	ing	suita	.ble
constraint					
	es (CO): Student will be able to				
	comprehensive understanding of the various phases of C				
	systems, from digital logic simulation to physical design, in	cludi	ing t	est a	and
verification					
I .	ate knowledge and understanding of fundamental concepts in CAD) and	l to e	stabl	ish
	for CAD tool development and enhancement.				
	he application of fundamentals of VLSI technologies				
	the implemented design for area, timing and power by applying sui				ıts.
UNIT - I				Hrs:	
I .	LSI Design Cycle, New Trends in VLSI Design Cycle, Physical De	sign	Cyc	le, N	ew
	al Design Cycle, Design Styles, System Packaging Styles.	-		**	
UNIT - II				Hrs:	
	artitioning, Pin Assignment and Placement: Partitioning – Problems			ıulatı	on,
	Partitioning algorithms, Kernighan-Lin Algorithm, Simulated Anne				
UNIT - III				Hrs:	
	Floor Planning – Problem formulation, Classification of floor plan				
1	floor planning, Rectangular Dualization, Pin Assignment – Prob	lem	torm	ıulatı	on,
	pin assignment algorithms, General and channel Pin assignments.	-		**	
UNIT - IV				Hrs:	
	Routing: Placement–Problem formulation, Classification of place	ment	t algo	orithi	ns,
	d placement algorithms.	C1	· · · · ·	. 4 !	
	and Detailed Routing: Global Routing – Problem formulation,				
	algorithms, Maze routing algorithms, Detailed Routing – Problems	em	IOIII	iuiaii	on,
UNIT - V	routing algorithms, Single layer routing algorithms.	Lac	turo	Llra	
	Automation of FPGAs and MCMs: FPGA Technologies, Physi			Hrs:	
•	itioning, Routing – Routing Algorithm for the Non-Segmented		•	•	
1	he Segmented Model; Introduction to MCM Technologies, MCM				_
Cycle.	ie beginemed wioder, indoduction to wiew reciniologies, wew	1 11y	sical	DCS.	ıgıı
Textbooks:					
	for VLSI Physical Design Automation by Naveed Shervani,3	3 rd Fd	lition	20	05
1. Taigoriumis	ioi vebi i nysicai besign radomadon by ivaveed biletvam,	, Eu	111011	, 20	υ,

2. CMOS Digital Integrated Circuits Analysis and Design - Sung-Mo Kang, Yusuf Leblebici,

Springer International Edition.

TMH, 3rd Ed., 2011.



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COMMON COURSE STRUCTURE & SYLLABI

- 1. VLSI Physical Design Automation-Theory and Practice by Sadiq M Sait, Habib Youssef, World Scientific.
- 2. Algorithms for VLSI Design Automation, S. H. Gerez, 1999, Wiley student Edition, John Wiley and Sons (Asia) Pvt. Ltd.
- 3. VLSI Physical Design Automation by Sung Kyu Lim, Springer International Edition



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COMMON COURSE STRUCTURE & SYLLABI

Course Code	DEVICE MODELLING	L	T	P	C
21D57104a		3	0	0	3
	Semester			I	
Course Objectiv					
	tand the physics of 2-terminal MOS operation and its characteristic				
	tand the physics of 4-terminal MOSFET operation and its character	istic	S.		
	e the SOI MOSFET electrical characteristics.				
	es (CO): Student will be able to				
 Understar 	nd the physics of 2-terminal MOS operation and its characteristics				
 Understar 	nd the physics of 4-terminal MOSFET operation and its characterist	ics.			
 Analyze t 	he SOI MOSFET electrical characteristics.				
UNIT - I		Le	cture	Hrs:	
2-terminal MOS	device: threshold voltage modelling (ideal case as well as consider	ing	the e	ffects	of
Qf, Φms and Dit.).	_			
UNIT - II		Le	cture	Hrs:	
C-V characterist	cs (ideal case as well as taking into account the effects of Qf, Φn	ns a	nd D	it);M	OS
capacitor as a di	agnostic tool (measurement of non-uniform doping profile, estimate	atior	of (Qf, 4	ms
and Dit)					
UNIT - III		Le	cture	Hrs:	
4-terminal MOS	FET: threshold voltage (considering the substrate bias); abov	e tl	resh	old	I-V
	E level 1,2,3 and 4).				
UNIT - IV				Hrs:	
	rrent model; scaling; effect of threshold tailoring implant (analyti				
	e using box approximation); buried channel MOSFET. Short cha	anne	1, D	IBL a	and
	ects; small signal analysis of MOSFETs (Meyer's model)				
UNIT - V				Hrs:	
	Basic structure; threshold voltage modelling Advanced topics:	ho	t ca	rriers	in
	Ms; CCDs; high-K gate dielectrics.				
Textbooks:					
	sics of Semiconductor Devices, (2e), Wiley Eastern, 1981.				
	Fundamentals of Nanotransistors, World Scientific Publishing Co	Pte :	Ltd		
2017.					
Reference Book					
	Operation and Modelling of the MOS Transistor, McGraw-Hill, 19	87.			
	t-carrier Effects in MOS Trasistors, Academic Press, 1995.				
3. J. P. Colinge, '	'FinFETs and Other Multi-Gate Transistors," Springer. 2009				



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COMMON COURSE STRUCTURE & SYLLABI

Course Code	FPGA ARCHITECTURES AND APPLICATIONS	L	T	P	C			
21D57104b		3	0	0	3			
	Semester]	[
Course Objectives:								
To acquire k	nowledge about various architectures and device technologies of	PLI	D's.					
• To comprehend FPGA Architectures.								
• To analyze System level Design and their application for Combinational and Sequential								

- Circuits.To familiarize with Anti-Fuse Programmed FPGAs.
- To apply knowledge of this subject for various design applications.

Course Outcomes (CO): Student will be able to

- Acquire knowledge about various architectures and device technologies of PLD's.
- Comprehend FPGA Architectures.
- Analyze System level Design and their application for Combinational and Sequential Circuits.
- Familiarize with Anti-Fuse Programmed FPGAs.
- Apply knowledge of this subject for various design applications.

UNIT - I Lecture Hrs:

Introduction to Programmable Logic Devices: Introduction, Simple Programmable Logic Devices

- Read Only Memories, Programmable Logic Arrays, Programmable Array Logic, Programmable Logic Devices/Generic Array Logic; Complex Programmable Logic Devices—Architecture of Xilinx Cool Runner XCR3064XL CPLD, CPLD Implementation of a Parallel Adder with Accumulation.

UNIT - II Field Programmable Gate Arrays Lecture Hrs:

UNIT - II Field Programmable Gate Arrays

Field Programmable Gate Arrays: Organization of FPGAs, FPGA Programming Technologies, Programmable Logic Block Architectures, Programmable Interconnects, and Programmable I/O blocks in FPGAs, Dedicated Specialized Components of FPGAs, and Applications of FPGAs.

UNIT - III Lecture Hrs:

SRAM Programmable FPGAs:Introduction, Programming Technology, Device Architecture, the Xilinx XC2000, XC3000 and XC4000 Architectures.

UNIT - IV Lecture Hrs:

Anti-Fuse Programmed FPGAs:Introduction, Programming Technology, Device Architecture, The Actel ACT1, ACT2 and ACT3 Architectures.

UNIT - V Lecture Hrs:

Design Applications: General Design Issues, Counter Examples, A Fast Video Controller, A Position Tracker for a Robot Manipulator, A Fast DMA Controller, Designing Counters with ACT devices, Designing Adders and Accumulators with the ACT Architecture

Textbooks:

- 1. Field Programmable Gate Array Technology Stephen M. Trimberger, Springer International Edition.
- 2. Digital Systems Design Charles H. Roth Jr, LizyKurian John, Cengage Learning.

- 1. Field Programmable Gate Arrays-John V.Oldfield, Richard C.Dorf, Wiley India.
- 2. Digital Design Using Field Programmable Gate Arrays Pak K. Chan/SamihaMourad, Pearson Low Price Edition.
- 3. Digital Systems Design with FPGAs and CPLDs-Ian Grout, Elsevier, Newnes.
- 4. FPGA based System Design-Wayne Wolf, Prentice Hall Modern Semiconductor Design Series.



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COMMON COURSE STRUCTURE & SYLLABI

Course Code ASIC DESIGN I	LT	P	C
21D57104c	3 0	0	3
Semester		[
Course Objectives:			
 To understand different types of ASICs and their libraries. 			
 To understand about programmable ASICs, I/O modules and their interconnects 	S.		
To familiarize different methods of software ASIC design their simulation	on, test	ing a	and
construction of ASICs.			
Course Outcomes (CO): Student will be able to			
Understand different types of ASICs and their libraries.			
• Understand about programmable ASICs, I/O modules and their interconnects.			
Familiarize different methods of software ASIC design their simulation	n, testi	ng a	and
construction of ASICs.	,	υ	
	Lecture	Hrs:	
Introduction to ASICs: Types of ASICs, Design Flow, Case Study, Economics of	f ASIC:	s. AS	SIC
Cell Libraries, Transistors as resistors, Transistor Parasitic Capacitance, Logical Effor			
Design, Library Architecture, Gate-Array Design, Standard Cell Design, Data Path Cell			
	Lecture		
Programmable ASICs and Programmable ASIC Logic Cells: The Anti fuse, Static	Ram, I	EPRO	DM
and EEPROM Technology, Practical Issues, Specifications, PREDP Benchmarks, FPO			
Actel ACT, Xilinx LCA, Altera Flex, Altera Max.			
UNIT - III	Lecture	Hrs:	
I/O Cells and Interconnects & Programmable ASIC Design Software: DC Outp	ut, AC	Outp	out,
DC input, AC input, Clock input, Power input, Xilinx I/O block, Other I/O Cells, Act			
LCA, Xilinx EPLD, Altera Max 5000 and 7000, Altera Max 9000, Altera FLEX, D	esign S	yster	ms,
Logic Synthesis, The Half gate ASIC.			
UNIT - IV	Lecture	Hrs:	
Low Level Design Entry and Logic Synthesis: Schematic Entry, Low level Design	gn Lar	iguag	ges,
PLA Tools, EDIF, A logic synthesis example, A Comparator/MUX, Inside a Log	gic Synt	hesiz	zer,
Synthesis of Viterbi Decoder, Verilog and Logic synthesis, VHDL and Logic Synthesis			
Machine Synthesis, Memory Synthesis, The Engine Controller, Performance Dri	ven Sy	nthes	sis,
Optimization of the viterbi decoder.			
UNIT - V	Lecture	Hrs:	
Simulation, Test and ASIC Construction: Types of Simulation, The Comparator/N	MUX E	xamp	ple,
Logic Systems, How Logic Simulation Works, Cell Models, Delay Models, Static Ti	_	-	
Formal Verification, Switch Level Simulation, Transistor Level Simulation, The imp			
Boundary Scan Test, Faults, Faults Simulation, Automatic Test Pattern Generator, Sca			
	no Fei	imati	:
Self-Test, A simple test Example, Physical Design, CAD Tools, System Partitioning	ng, Ls	ımatı	mg
Self-Test, A simple test Example, Physical Design, CAD Tools, System Partitionin ASIC Size, Power Dissipation, FPGA Partitioning, Partitioning Methods	ng, Lst	ımatı	mg
Self-Test, A simple test Example, Physical Design, CAD Tools, System Partitioning			

1. HimanshuBhatnagar, "Advanced ASIC Chip Synthesis using Synopsis Design Compiler", 2nd Edition, Kluwer Academic, 2001.

2. L.J.Herbst, "Integrated Circuit Engineering", Oxford Science Publications, 1996.



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

COMMON COURSE STRUCTURE & SYLLABI

Course Code	CMOS ANALOG IC DESIGN LAB	L	T	P	С
21D57105		0	0	4	2
	Semester			I	

Course Objectives:

- To explain the VLSI Design Methodologies using VLSI design tool.
- To grasp the significance of various CMOS analog circuits in full-custom IC Design flow
- To explain the Physical Verification in Layout Design
- To fully appreciate the design and analyze of analog and mixed signal simulation
- To grasp the Significance of Pre-Layout Simulation and Post-Layout Simulation

Course Outcomes (CO):

- Explain the VLSI Design Methodologies using VLSI design tool.
- Grasp the significance of various CMOS analog circuits in full-custom IC Design flow
- Explain the Physical Verification in Layout Design
- Fully appreciate the design and analyze of analog and mixed signal simulation
- Grasp the Significance of Pre-Layout Simulation and Post-Layout Simulation

List of Experiments:

- The students are required to design and implement any **TEN** Experiments using CMOS 130nm Technology.
- The students are required to implement LAYOUTS of any **SIX** Experiments using CMOS 130nm Technology and Compare the results with Pre-Layout Simulation.
- 1. MOS Device Characterization and parametric analysis
- 2. Common Source Amplifier
- 3. Common Source Amplifier with source degeneration
- 4. Cascode amplifier
- 5. Simple current mirror
- 6. Cascode current mirror.
- 7. Wilson current mirror.
- 8. Differential Amplifier
- 9. Operational Amplifier
- 10. Sample and Hold Circuit
- 11. Direct-conversion ADC
- 12. R-2R Ladder Type DAC

Lab Requirements:

Software:

Mentor Graphics – Pyxis Schematic, IC Station, Calibre, ELDO Simulator

Hardware:

Personal Computer with necessary peripherals, configuration and operating System.



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

COMMON COURSE STRUCTURE & SYLLABI

Course Code	CMOS DIGITAL IC DESIGN LAB		L	T	P	С
21D57106			0	0	4	2
	Semes	ster			I	

Course Objectives:

- To explain the VLSI Design Methodologies using any VLSI design tool.
- To grasp the significance of various design logic Circuits in full-custom IC Design.
- To explain the Physical Verification in Layout Extraction.
- To fully appreciate the design and analyze of CMOS Digital Circuits.
- To grasp the Significance of Pre-Layout Simulation and Post-Layout Simulation.

Course Outcomes (CO):

- Explain the VLSI Design Methodologies using any VLSI design tool.
- Grasp the significance of various design logic Circuits in full-custom IC Design.
- Explain the Physical Verification in Layout Extraction.
- Fully appreciate the design and analyze of CMOS Digital Circuits.

Grasp the Significance of Pre-Layout Simulation and Post-Layout Simulation.

List of Experiments:

The students are required to design and implement the Circuit and Layout of any **TEN** Experiments using CMOS 130nm Technology.

- 1. Inverter Characteristics.
- 2. NAND and NOR Gate
- 3. XOR and XNOR Gate
- 4. 2:1 Multiplexer
- 5. Full Adder
- 6. RS-Latch
- 7. Clock Divider
- 8. JK-Flip Flop
- 9. Synchronous Counter
- 10. Asynchronous Counter
- 11.Static RAM Cell
- 12. Dynamic Logic Circuits
- 13. Linear Feedback Shift Register

Lab Requirements:

Software:

Mentor Graphics Tool/ Cadence/ Synopsys/Industry Equivalent Standard Software

Hardware

Personal Computer with necessary peripherals, configuration and operating System.



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

	RESEARCH METHODOLOGY AND IPR	L	T	P	C
21DRM101		2	0	0	2
	Semester			I	
Course Object					
	an appropriate research problem in their interesting domain.				
	tand ethical issues understand the Preparation of a research project th	esis rep	ort.		
	tand the Preparation of a research project thesis report				
 Unders 	tand the law of patent and copyrights.				
	tand the Adequate knowledge on IPR				
Course Outcor	nes (CO): Student will be able to				
 Analyz 	e research related information				
	research ethics				
 Unders 	tand that today's world is controlled by Computer, Information Te	chnolog	gy, but	tom	orro
	vill be ruled by ideas, concept, and creativity.				
 Unders 	tanding that when IPR would take such important place in growth of	individ	uals &	natio	n, it
	s to emphasis the need of information about Intellectual Property R				
student	s in general & engineering in particular.		-		
 Unders 	tand that IPR protection provides an incentive to inventors for	further 1	researc	h wor	k an
investn	' D 0 D 1' 1 1 1 4 4' C 11 4 1 4	1 .	4 1-	•	
	nent in R & D, which leads to creation of new and better products	, and in	turn c	rings	abou
	hent in $R \& D$, which leads to creation of new and better products ic growth and social benefits.	, and in	turn c	rings	abou
UNIT - I	nic growth and social benefits. Lecture Hrs	•			
UNIT - I	nic growth and social benefits.	•			
UNIT - I Meaning of re	nic growth and social benefits. Lecture Hrs	:	f a go	od res	searc
UNIT - I Meaning of re problem, Errors	nic growth and social benefits. Lecture Hrs search problem, Sources of research problem, Criteria Character	: ristics o	f a go m. Ap	od res	searc
UNIT - I Meaning of re problem, Errors investigation	search problem, Sources of research problem, Criteria Character is in selecting a research problem, scope, and objectives of research following solutions for research problem, data collection, analysis,	: ristics o	f a go m. Ap	od res	searc
UNIT - I Meaning of re problem, Errors investigation of instrumentation	search problem, Sources of research problem, Criteria Character is in selecting a research problem, scope, and objectives of research following solutions for research problem, data collection, analysis,	: ristics on problem interpre	f a go m. Ap	od res	searc
UNIT - I Meaning of re problem, Errors investigation of instrumentation UNIT - II	search problem, Sources of research problem, Criteria Characters in selecting a research problem, scope, and objectives of research of solutions for research problem, data collection, analysis, s	: ristics on proble interpre	f a go m. Apetation,	od resoproaci	searc hes (
UNIT - I Meaning of re problem, Errors investigation of instrumentation UNIT - II Effective literat	Lecture Hrs search problem, Sources of research problem, Criteria Character is in selecting a research problem, scope, and objectives of research of solutions for research problem, data collection, analysis, s Lecture Hrs ture studies approaches, analysis Plagiarism, Research ethics, Effectives Lecture Hrs	: ristics of proble interpretive tech	f a go m. Apetation,	od resoproaci Nece	searches (essai
WNIT - I Meaning of reproblem, Errorsinvestigation of instrumentation UNIT - II Effective literate write report	Lecture Hrs search problem, Sources of research problem, Criteria Character is in selecting a research problem, scope, and objectives of research of solutions for research problem, data collection, analysis, s Lecture Hrs ture studies approaches, analysis Plagiarism, Research ethics, Effect, Paper Developing a Research Proposal, Format of research proposal,	: ristics of proble interpretive tech	f a go m. Apetation,	od resoproaci Nece	searc hes dessar
UNIT - I Meaning of re problem, Errors investigation of instrumentation UNIT - II Effective literate to write report assessment by a	Lecture Hrs search problem, Sources of research problem, Criteria Character is in selecting a research problem, scope, and objectives of research of solutions for research problem, data collection, analysis, s Lecture Hrs ture studies approaches, analysis Plagiarism, Research ethics, Effectives Lecture Hrs	: ristics on proble interpretive tech	f a go m. Apetation,	od resoproaci Nece	searches cessar
UNIT - I Meaning of reproblem, Errors investigation of instrumentation UNIT - II Effective literate to write report assessment by a UNIT - III	Lecture Hrs search problem, Sources of research problem, Criteria Character is in selecting a research problem, scope, and objectives of research of solutions for research problem, data collection, analysis, search studies approaches, analysis Plagiarism, Research ethics, Effect, Paper Developing a Research Proposal, Format of research programmers of the review committee. Lecture Hrs	: ristics of proble interpretive technoposal,	f a gom. Apetation,	od resoproaci Neco	searches ches ches ches ches ches ches ches
WNIT - I Meaning of reproblem, Errors investigation of instrumentation UNIT - II Effective literate to write report assessment by a UNIT - III Nature of Intelli	Lecture Hrs search problem, Sources of research problem, Criteria Character is in selecting a research problem, scope, and objectives of research of solutions for research problem, data collection, analysis, Lecture Hrs ture studies approaches, analysis Plagiarism, Research ethics, Effect, Paper Developing a Research Proposal, Format of research proposal review committee. Lecture Hrs ectual Property: Patents, Designs, Trade and Copyright. Process of P	ristics on proble interpretions to the composal, and compo	f a gom. Apetation,	od resproach Neco	searches dessar
WNIT - I Meaning of reproblem, Errors investigation of instrumentation UNIT - II Effective literate write report assessment by a UNIT - III Nature of Intell technological residues.	Lecture Hrs search problem, Sources of research problem, Criteria Character is in selecting a research problem, scope, and objectives of research of solutions for research problem, data collection, analysis, Lecture Hrs ture studies approaches, analysis Plagiarism, Research ethics, Effect, Paper Developing a Research Proposal, Format of research proposal review committee. Lecture Hrs ectual Property: Patents, Designs, Trade and Copyright. Process of Pesearch, innovation, patenting, development. International Scenario	ristics on proble interpretions to the composal, and compo	f a gom. Apetation,	od resproach Neco	searches dessar
WNIT - I Meaning of reproblem, Errors investigation of instrumentation UNIT - II Effective literate to write report assessment by a UNIT - III Nature of Intellitechnological report on Intellectual 1	Lecture Hrs search problem, Sources of research problem, Criteria Character in selecting a research problem, scope, and objectives of research of solutions for research problem, data collection, analysis, search studies approaches, analysis Plagiarism, Research ethics, Effect, Paper Developing a Research Proposal, Format of research proposal review committee. Lecture Hrs Lecture Hrs ectual Property: Patents, Designs, Trade and Copyright. Process of Pesearch, innovation, patenting, development. International Scenario Property. Procedure for grants of patents, Patenting under PCT.	ristics on proble interpretive techoposal, and attenting	f a gom. Apetation,	od resproach Neco	searches essan
WNIT - I Meaning of reproblem, Errors investigation of instrumentation UNIT - II Effective literate to write report assessment by a UNIT - III Nature of Intellitechnological report on Intellectual I UNIT - IV	Lecture Hrs search problem, Sources of research problem, Criteria Character in selecting a research problem, scope, and objectives of research of solutions for research problem, data collection, analysis, search studies approaches, analysis Plagiarism, Research ethics, Effect, Paper Developing a Research Proposal, Format of research proposal review committee. Lecture Hrs Lecture Hrs ectual Property: Patents, Designs, Trade and Copyright. Process of Pesearch, innovation, patenting, development. International Scenario Property. Procedure for grants of patents, Patenting under PCT. Lecture Hrs	: ristics on proble interpretive techoposal, artenting: International in	f a go m. Apetation, nnical v a prese	od resperoaci Neces writing entatio	searce hes contents and the season s, ho no are
WNIT - I Meaning of reproblem, Errors investigation of instrumentation UNIT - II Effective literate to write report assessment by a UNIT - III Nature of Intellitechnological report on Intellectual I UNIT - IV	Lecture Hrs search problem, Sources of research problem, Criteria Character is in selecting a research problem, scope, and objectives of research of solutions for research problem, data collection, analysis, search ethics, analysis Plagiarism, Research ethics, Effect, Paper Developing a Research Proposal, Format of research proposal review committee. Lecture Hrs ectual Property: Patents, Designs, Trade and Copyright. Process of Pesearch, innovation, patenting, development. International Scenario Property. Procedure for grants of patents, Patenting under PCT. Lecture Hrs Scope of Patent Rights. Licensing and transfer of technology. Patent	: ristics on proble interpretive techoposal, artenting: International in	f a go m. Apetation, nnical v a prese	od resperoaci Neces writing entatio	searches hes sessa g, ho n ar

New Developments in IPR: Administration of Patent System. New developments in IPR; IPR of Biological Systems, Computer Software etc. Traditional knowledge Case Studies, IPR and IITs.

Textbooks:

- 1. Stuart Melville and Wayne Goddard, "Research methodology: an introduction for science & engineering students"
- 2. Wayne Goddard and Stuart Melville, "Research Methodology: An Introduction"

- 1. Ranjit Kumar, 2nd Edition, "Research Methodology: A Step by Step Guide for beginners"
- 2. Halbert, "Resisting Intellectual Property", Taylor & Drancis Ltd ,2007.
- 3. Mayall, "Industrial Design", McGraw Hill, 1992.
- 4. Niebel, "Product Design", McGraw Hill, 1974.
- 5. Asimov, "Introduction to Design", Prentice Hall, 1962.



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

COMMON COURSE STRUCTURE & SYLLABI

6. Robert P. Merges, Peter S. Menell, Mark A. Lemley, "Intellectual Property in New Technological Age", 2016.



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

COMMON COURSE STRUCTURE & SYLLABI

Course Code	CMOS MIXED SIGNAL IC DESIGN	L	T	P	C
21D57201		3	0	0	3
	Semester		I	I	
Course Objecti	ves:				
 To demon 	nstrate first order filter with least interference				
	d the concept of phase locked loop for designing PLL applicatio	n w	ith m	inim	um
	considering non ideal effects.				
•	n different A/D, D/A, modulators, demodulators and different fil	lter	for r	eal ti	me
application					
	es (CO): Student will be able to				
	rate first order filter with least interference				
	ne concept of phase locked loop for designing PLL application wit	h m	inimı	ım ji	tter
-	lering non ideal effects.				
	lifferent A/D, D/A, modulators, demodulators and different filt	er f	or re	eal ti	me
application	ons				
UNIT - I			cture		
	citor Circuits: Introduction to Switched Capacitor circuits- basic				
	Analysis, Non-ideal effects in switched capacitor circuits, Sw	/itch	ed c	apacı	itor
	order filters, Switch sharing, biquad filters.	•		**	
UNIT – II			cture		-
	oop (PLL): Basic PLL topology, Dynamics of simple PLL, Cha	_	-		
•	n, Phase/Frequency detector and charge pump, Basic charge pump		L, N	on-10	ieai
UNIT - III	PFD/CP non-idealities, Jitter in PLLs, Delay locked loops, applicati		cture	Hree	
	: Fundamentals DC and dynamic specifications, Quantization no				ate
	Decoder based converters, Binary-Scaled converters, Thermometer				
Hybrid convertes	· · · · · · · · · · · · · · · · · · ·	COC	ic co.	1 / C1 (015,
UNIT - IV		Leo	cture	Hrs:	
	rters: Nyquist Rate A/D Converters Successive approximation				ash
	-step A/D converters, Interpolating A/D converters, Folding				
	onverters, Sigma Delta A/D coverters, Time- interleaved converters.				,
UNIT - V			cture	Hrs:	
Oversampling	Converters: Noise shaping modulators, Decimating filters and int	erpo	lating	g filte	ers,
Higher order mo	dulators, Delta sigma modulators with multi bit quantizers, Delta sig	gma	D/A		
Textbooks:					
1. Design of Ana	alog CMOS Integrated Circuits- BehzadRazavi, TMH Edition, 2002				
2. CMOS Analo	g Circuit Design - Philip E. Allen and Douglas R. Holberg, Oxford	Uni	versit	y Pre	ess,
	cond Edition/Indian Edition, 2010.				
	ated Circuit Design- David A. Johns, Ken Martin, Wiley Student Ed	litio	n, 20	13	
Reference Book					
-	rated Analog-to- Digital and Digital-to-Analog converters- Rudy V	Van	De F	Plasso	he,
	ic Publishers, 2003				
	Delta-Sigma Data converters-Richard Schreier, Wiley Inter science	, 20	05.		
3. CMOS Mixed	-Signal Circuit Design - R. Jacob Baker, Wiley Interscience,2009				



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

COMMON COURSE STRUCTURE & SYLLABI

Course Code	PHYSICAL DESIGN AUTOMATION	L	T	P	C
21D57202		3	0	0	3
	Semester		I	[
Course Objecti					
	erstand relation between automation algorithms and constraints	pose	d by	/ VI	_SI
technolog					
_	algorithms to meet critical design parameters.				
 To design 	n area efficient logics by employing different routing algorithms and	l shap	e fui	nctio	ns.
 To simul 	ate and synthesis different combinational and sequential logics.				
Course Outcom	nes (CO): Student will be able to				
 Understa 	nd relation between automation algorithms and constraints	posed	l by	VI	_SI
technolo	gy.				
 Adopt al 	gorithms to meet critical design parameters.				
_	rea efficient logics by employing different routing algorithms and sh	nape f	unct	ions.	
•	and synthesis different combinational and sequential logics.	•			
UNIT - I		Lect	ture l	Hrs:	
VLSI Design	Automation Tools: Algorithms and system design, Structural a	nd lo	ogic	desi	gn,
_	design, Layout design, Verification methods, Design management to		U		,
UNIT - II			ture l	Hrs:	
Layout: Comp	action, placement and routing, Design rules, symbolic layout,	App	licat	ions	of
	ormulation methods, Algorithms for constrained graph com				
representation, V	Wire length estimation, Placement algorithms, Partitioning algorithm	is.	•		
UNIT - III		Lect	ture l	Hrs:	
Floor planning	and routing: Floor planning concepts, Shape functions and floor	plan	ning	sizi	ng,
	area routing, Channel routing, global routing and its algorithms.	•	Ü		O.
UNIT - IV		Lect	ture l	Hrs:	
Simulation and	Logic Synthesis: Gate level and switch level modeling and simula	tion,	Intro	duct	ion
	· · · · · · · · · · · · · · · · · ·	constr			and
	wo level logic synthesis.				
UNIT - V		Lect	ture l	Hrs:	
High-Level Syr	nthesis: Hardware model for high level synthesis, internal repres	entati	on (of in	put
algorithms, Allo	ocation, assignment and scheduling, scheduling algorithms, Aspec	ts of	assig	gnme	nt,
High level trans	formations.				
Textbooks:					
1. S.H. Gerez, A	Ilgorithms for VLSI Design Automation, John Wiley, 1998.				
2. N.A. Sherwar	ni, Algorithms for VLSI Physical Design Automation, (3/e), Kluwer,	, 1999	€.		
Reference Book	KS:				
	Youssef, VLSI Physical Design Automation, World scientific, 1999.				
	h, Introduction to VLSI Physical Design, McGraw Hill (IE), 1996				
	, , , , , , , , , , , , , , , , , , , ,				



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

Course Code	SoC TESTING AND VERIFICATION	L	T	P	C
21D57203a		3	0	0	3
	Semester		I	I	
Course Objecti	ves:				
 To under 	erstand the concepts of faults and testing in SoC				
 To impl 	ement the faults using simulation tools				
To analy	yze BIST systems				
Course Outcon	nes (CO): Student will be able to				
 Underst 	and the concepts of faults and testing in SoC				
Implem	ent the faults using simulation tools				
 Analyze 	BIST systems				
UNIT - I		Lec	cture	Hrs:	
	Testing: Testing Philosophy, Role of Testing, Digital and				
	Technology Trends affecting Testing, Types of Testing,				
Defects, Errors	and Faults, Functional Versus Structural Testing, Levels of Fau	lt M	odels	, Sin	gle
Stuck-at Fault.					
UNIT - II			cture		
	It Simulation: Simulation for Design Verification and Test Evaluation				ing
Circuits for Sim	ulation, Algorithms for True-value Simulation, Algorithms for Fault	Sin	ıulati	on.	
UNIT - III		Lec	cture	Hrs:	
Testability Me	asures: SCOAP Controllability and Observablity, High L	evel	Te	stabi	lity
Measures, Dig	ital DFT and Scan Design: Ad-Hoc DFT Methods, Scan Des	sign,	Part	ial-S	can
Design, Variation	ons of Scan.				
UNIT - IV			cture		
	est: The Economic Case for BIST, Random Logic BIST: Definition				
	ion, Response Compaction, Built-In Logic Block Observers, Test-			k, To	est-
Per-Scan BIST S	Systems, Circular Self Test Path System, Memory BIST, Delay Faul				
UNIT - V			cture		
	Standard: Motivation, System Configuration with Boundary Scan				
	ndary Scan Test Instructions, Pin Constraints of the Standard,	Bo	undai	y So	can
	guage: BDSL Description Components, Pin Descriptions.				
Textbooks:				1 3 4.	1
	ll, V. D. Agrawal, "Essentials of Electronic Testing for Digital, Me	mor	y and	1 IVI17	cea
	rcuits", Kluwer Academic Pulishers.	ام ا	og i ~	,, T-	
Publishing House	ici, M.A.Breuer and A.D Friedman, "Digital Systems and Testab	וט ט	esign	. , ја	100
Reference Bool					
	igital Circuits Testing and Testability", Academic Press.				
1. F.K. Laia, D	ignal Circuits resuling and restability, Academic riess.				



structures.

JAWAHARLAL NEHRU TECHNOLOGICAL UNIVERSITY ANANTAPUR (Established by Govt. of A.P., ACT No.30 of 2008) ANANTHAPURAMU – 515 002 (A.P) INDIA

M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

COMMON COURSE STRUCTURE & SYLLABI

Course Code	SEMICONDUCTOR MEMORY DESIGN AND TESTING	L	Т	P	C
21D57203b	SEMICONDUCTOR MEMORT DESIGN AND TESTING	3	0	0	3
210372030	Semester	3	II		3
	Semester				
Course Objectiv	ves:				
•	rstand different types of memories, their architectural and d	iffer	ent 1	oack	ing
	s of memories.		1		C
• To build t	fault models for memory testing.				
	te different parameters that lead malfunctioning of memories.				
	n reliable memories with efficient architecture to improve proc	esse	s tim	es a	and
power.					
Course Outcom	es (CO): Student will be able to				
• Get com	plete knowledge regarding different types of memories, their	archi	tectu	ral a	and
different	packing techniques of memories.				
 Build fau 	lt models for memory testing.				
• Analyze	different parameters that lead malfunctioning of memories.				
 Design re 	liable memories with efficient architecture to improve processes tim	nes a	nd po	wer.	
UNIT - I		Lec	ture I	Hrs:	
Random Acces	s Memory Technologies :SRAM - SRAM Cell structures	, M	OS	SRA	4M
	OS SRAM cell and peripheral circuit operation, Bipolar SRAM to				
	anced SRAM architectures and technologies, Application specific				
	logy development, CMOS DRAM, DRAM cell theory and advance				
	M, soft error failure in DRAM, Advanced DRAM design a	ınd	archi	tectu	ıre,
Application spec	ific DRAM.				
* * * * * * * * * * * * * * * * * * * *		_			
UNIT - II			ture I		
UNIT - II Non-volatile M	emories: Masked ROMs, High density ROM, PROM, Bipola	r Ro	OM,	CM	OS
UNIT - II Non-volatile M PROMS, EPRO	M, Floating gate EPROM cell, One time programmable EPR	r Ro OM	OM, EE	CM PRO	OS OM,
UNIT - II Non-volatile M PROMS, EPRO EEPROM techn	M, Floating gate EPROM cell, One time programmable EPR nology and architecture, Non-volatile SRAM, Flash Memoria	r Ro OM	OM, EE	CM PRO	OS OM,
UNIT - II Non-volatile M PROMS, EPRO EEPROM techr EEPROM), adva	M, Floating gate EPROM cell, One time programmable EPR	r RO OM, es (OM, EEI	CM PRO DM	OS OM,
UNIT - II Non-volatile M PROMS, EPRO EEPROM techr EEPROM), adva UNIT - III	M, Floating gate EPROM cell, One time programmable EPR nology and architecture, Non-volatile SRAM, Flash Memorianced Flash memory architecture	r RO OM es (OM, EEI EPRO ture I	CM PRO DM Hrs:	OS OM,
UNIT - II Non-volatile M PROMS, EPRO EEPROM techr EEPROM), adva UNIT - III Memory Fault M	M, Floating gate EPROM cell, One time programmable EPR nology and architecture, Non-volatile SRAM, Flash Memorianced Flash memory architecture Modeling Testing and Memory Design for Testability and Fault	r ROMes (OM, EER EPR ture I	CM PRO DM Hrs:	OS OM, or
UNIT - II Non-volatile M PROMS, EPRO EEPROM techn EEPROM), adva UNIT - III Memory Fault M RAM fault mod	M, Floating gate EPROM cell, One time programmable EPR nology and architecture, Non-volatile SRAM, Flash Memorianced Flash memory architecture Modeling Testing and Memory Design for Testability and Fault leling, Electrical testing, Pseudo Random testing, Megabit DRA	r ROMes (Lecomoder Tole M T	OM, EER EPR ture I	CM PRO DM Hrs: e:	OS OM, or
UNIT - II Non-volatile M PROMS, EPRO EEPROM techr EEPROM), adva UNIT - III Memory Fault M RAM fault mod volatile memory	My Floating gate EPROM cell, One time programmable EPR mology and architecture, Non-volatile SRAM, Flash Memorianced Flash memory architecture Modeling Testing and Memory Design for Testability and Fault leling, Electrical testing, Pseudo Random testing, Megabit DRAM modeling and testing, IDDQ fault modeling and testing, App	r ROMes (Lecomoder Tole M T	OM, EER EPR ture I	CM PRO DM Hrs: e:	OS OM, or
UNIT - II Non-volatile M PROMS, EPRO EEPROM techr EEPROM), adva UNIT - III Memory Fault M RAM fault mod volatile memory memory testing,	M, Floating gate EPROM cell, One time programmable EPR nology and architecture, Non-volatile SRAM, Flash Memorianced Flash memory architecture Modeling Testing and Memory Design for Testability and Fault leling, Electrical testing, Pseudo Random testing, Megabit DRA	r ROMes (Lec Tole M Tolicat	OM, EEI EPRO ture I rance esting	CM PRO OM Hrs: e: g, no	OS OM, or
UNIT - II Non-volatile M PROMS, EPRO EEPROM techr EEPROM), adva UNIT - III Memory Fault M RAM fault mod volatile memory memory testing, UNIT - IV	M, Floating gate EPROM cell, One time programmable EPR cology and architecture, Non-volatile SRAM, Flash Memorianced Flash memory architecture Modeling Testing and Memory Design for Testability and Fault celing, Electrical testing, Pseudo Random testing, Megabit DRAM modeling and testing, IDDQ fault modeling and testing, App RAM fault modeling, BIST techniques for memory.	r RO OM, es (Lec Tole M T Dlicat	OM, EEPRO ture I rance esting ion s	CM PRO DM Hrs: e: g, no speci	OS OM, or on- ific
UNIT - II Non-volatile M PROMS, EPRO EEPROM techn EEPROM), adva UNIT - III Memory Fault M RAM fault mod volatile memory memory testing, UNIT - IV Semiconductor	My Floating gate EPROM cell, One time programmable EPR mology and architecture, Non-volatile SRAM, Flash Memorianced Flash memory architecture Modeling Testing and Memory Design for Testability and Fault leling, Electrical testing, Pseudo Random testing, Megabit DRAM modeling and testing, IDDQ fault modeling and testing, App	Lec Tole M Tolicat Lec Gues	OM, EERO ture I rance esting ion s ture I	CM PRO OM Hrs: e: g, no speci	OS OM, or on- ific

UNIT - V Lecture Hrs:

Radiation effects, Single Event Phenomenon (SEP), Radiation Hardening techniques, Radiation Hardening Process and Design Issues, Radiation Hardened Memory characteristics, Radiation Hardness Assurance and Testing, Radiation Dosimetry, Water Level Radiation Testing and Test

Advanced Memory Technologies and High-density Memory Packing Technologies

Ferroelectric RAMs (FRAMs), GaAs FRAMs, Analog memories, magneto resistive RAMs (MRAMs), Experimental memory devices, Memory Hybrids and MCMs (2D), Memory Stacks and MCMs (3D), Memory MCM testing and reliability issues, Memory cards, High Density Memory



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

COMMON COURSE STRUCTURE & SYLLABI

Packaging Future Directions.

Textbooks:

- Semiconductor Memories Technology Ashok K. Sharma, 2002, Wiley.
 Advanced Semiconductor Memories Architecture, Design and Applications Ashok K. Sharma, 2002, Wiley.

Reference Books:

1. Modern Semiconductor Devices for Integrated Circuits – Chenming C Hu, First Edition. Prentice



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

COMMON COURSE STRUCTURE & SYLLABI

Course Code	MEMS SYSTEM DESIGN	L	T	P	C
21D57203c		3	0	0	3
	Semester		I	I	
Course Objective					
	and the basic concepts of MEMS technology and working of MEM				
	stand and select different materials for current MEMS devices	s an	d co	mpet	ing
-	es for future applications.				
	stand the concepts of fabrication process of MEMS, Design	an	d Pa	ckag	ing
Methodolo	••				
 To analyze 	e the various fabrication techniques in the manufacturing of MEMS	S De	vices		
<u> </u>	(00) 0, 1, , 311, 11,				
	s (CO): Student will be able to	1			
	d the basic concepts of MEMS technology and working of MEMS				
	d and select different materials for current MEMS devices	and	ı co	mpet	ıng
•	es for future applications.	0.00	1 Do	ماده م	
	d the concepts of fabrication process of MEMS, Design	anc	ı Pa	скад	mg
Methodolo		Varria	20		
UNIT - I	ne various fabrication techniques in the manufacturing of MEMS D		es. cture	Llege	—
	MEMS: Introduction to MEMS & Real world Sensor/Actuator				(D
	sensors). MEMS Sensors in Internet of Things (IoT), Bio-Medical				ID,
	sensors). WEIVIS Sensors in Internet of Timigs (101), Bio-Wedicur				
UNIT - II			cture		
	s and Their Properties: Materials (eg. Si, SiO2, SiN, Cr, Au,				
	perties: Young modulus, Poisson's ratio, density, piezo-resistive c				
	ctivity, Material Structure. Understanding Selection of material	erial	s ba	sed	on
applications.		-		**	
UNIT - III	4 V 1 V 1 V 1 V 1 V 1 V 1 V 1 V 1 V 1 V		ture		
	cesses – 1: Understanding MEMS Processes & Process parameter				
	ition, Ion Implantation & Diffusion, Annealing, Lithography	. U	naers	stana	ıng
UNIT - IV	rocesses based on Applications.	Τ	cture	I I.a.	
	2. He denotes die a MEMC Description & Description				
	cesses – 2: Understanding MEMS Processes & Process parameter Surface Micromachining, Die, Wire& Wafer Bonding, Die				
		ing,	Pac	ckagi	ng.
UNIT - V	ection of Fab processes based on Applications.	I ec	cture	Hre	
	Architecture, working and basic quantitative behaviour of Ca				cro
	ometers, Pressure Sensors, Micro mirrors in DMD, Ink				
	eps involved in Fabricating above devices.	jet	Print	C1 11C	uu
Textbooks:	po m. or. og m r norrenning no o to de trees.				
	on to Micro electromechanical Systems Engineering; 2nd Edition	n hv	N.V	Ialuf	K
	er: Artech House Inc	. J	1 1017.		
2 2	fo 1 True Tr ' 1 ' D 11' 1				

Reference Books:

1. Analysis and Design Principles of MEMS Devices – Minhang Bao; Publisher: Elsevier Science.

2. Practical MEMS - by Ville Kaajakari; Publisher: Small Gear Publishing

3. Micro system Design - by S. Senturia; Publisher: Springer



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

- 2. Fundamentals of Micro fabrication by M. Madou; Publisher:CRC Press; 2ndedition
- 3. Micro Electro Mechanical System Design by J. Allen; Publisher: CRC Press
- 4. Micro machined Transducers Sourcebook by G. Kovacs; Publisher: McGraw-Hill



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COMMON COURSE STRUCTURE & SYLLABI

Course Code	LOW POWER VLSI DESIGN	L	T	P	C
21D57204a		3	0	0	3
	Semester		I	I	
Course Objecti	ves:				
 To under 	stand the concepts of velocity saturation, Impact Ionization and Hot	Elec	ctron	Effe	ct
 To imple 	ment Low power design approaches for system level and circuit level	el me	easur	es.	
To design	n low power adders, multipliers and memories for efficient design of	f syst	tems.		
Course Outcom	nes (CO): Student will be able to				
Understa	nd the concepts of velocity saturation, Impact Ionization and Hot Ele	ectro	n Ef	fect	
	nt Low power design approaches for system level and circuit level n				
•	ow power adders, multipliers and memories for efficient design of sy				
UNIT - I	power waste, manapares and memories for exterem design of s		ture	Hrs:	
	Need for Low Power Circuit Design, Sources of Power Dissipat				and
	Dissipation, Short Circuit Power Dissipation, Glitching Power D				
	-Drain Induced Barrier Lowering and Punch Through, Surface Sca				
	act Ionization, Hot Electron Effect.		6,		
UNIT - II	,	Lec	ture	Hrs:	
	sign Approaches: Low-Power Design through Voltage Scaling – V	TCN	/IOS	circu	iits,
	uits, Architectural Level Approach —Pipelining and Paral			ocess	
	witched Capacitance Minimization Approaches: System Level N	Meas			_
* *	Mask level Measures.		Í		
UNIT - III		Lec	ture	Hrs:	
Low-Voltage	Low-Power Adders: Introduction, Standard Adder Cells,	CMO	OS	Adde	er's
Architectures –	Ripple Carry Adders, Carry Look Ahead Adders, Carry Select Ad	ders	, Car	ry Sa	ave
Adders, Low-V	oltage Low-Power Design Techniques - Trends of Technology an	nd P	ower	Sup	ply
Voltage, Low-V	oltage Low-Power Logic Styles.				
UNIT - IV		Lec	cture	Hrs:	
Low-Voltage 1	Low-Power Multipliers: Introduction, Overview of Multiplication	ation	ı, T	ypes	of
Multiplier Archi	tectures, Braun Multiplier, Baugh Wooley Multiplier, Booth Multip	lier,	Intro	oduct	ion
to Wallace Tree	Multiplier.				
UNIT - V		Lec	ture	Hrs:	
Low-Voltage L	ow-Power Memories: Basics of ROM, Low-Power ROM Technological	gy,]	Futu	re Tre	end
and Developme	nt of ROMs, Basics of SRAM, Memory Cell, Precharge and Equ	aliza	ition	Circ	uit,
Low-Power SR	AM Technologies, Basics of DRAM, Self-Refresh Circuit, Fu	ature	Tre	end a	and
Development of	DRAM.				
Textbooks:					
_	1 Integrated Circuits - Analysis and Design - Sung-Mo Kang,	Yusı	ıf Le	ebleb	ici,
TMH, 2011.					
	, Low-Power VLSI Subsystems – Kiat-Seng Yeo, Kaushik Roy, T	MH	Prof	essio	nal
Engineering.					

Reference Books:

- 1. Introduction to VLSI Systems: A Logic, Circuit and System Perspective Ming-BO Lin, CRC Press, 2011.
- 2.Low Power CMOS Design AnanthaChandrakasan, IEEE Press/Wiley International, 1998.
- 3. Low Power CMOS VLSI Circuit Design Kaushik Roy, Sharat C. Prasad, John Wiley & Sons, 2000.



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

COMMON COURSE STRUCTURE & SYLLABI

Course Code	IOT AND ITS APPLICATIONS	L	T	P	C
21D57204b		3	0	0	3
	Semester		I	I	
Course Objective	es:				
 To apply the 	he Knowledge in IOT Technologies and Data management.				
To determ	ine the values chains Perspective of M2M to IOT.				
To implem	ent the state of the Architecture of an IOT.				
 To compar 	re IOT Applications in Industrial & real world.				
	strate knowledge and understand the security and ethical issues of	an IC	T.		
Course Outcome	s (CO): Student will be able to				
 Apply the 	Knowledge in IOT Technologies and Data management.				
 Determine 	the values chains Perspective of M2M to IOT.				
 Implement 	the state of the Architecture of an IOT.				
 Compare I 	OT Applications in Industrial & real world.				
 Demonstra 	tte knowledge and understand the security and ethical issues of an	IOT.			
UNIT - I		Lec	cture	Hrs:	
	of IoT: Evolution of Internet of Things, Enabling Te				
1	M2M, IoT World Forum (IoTWF) and Alternative IoT models				
	Core IoT Functional Stack, Fog, Edge and Cloud in IoT, Function	onal	block	cs of	an
	ensors, Actuators, Smart Objects and Connecting Smart Objects.				
	view: Overview of IoT supported Hardware platforms such as: Ra	ispbe	erry p	oi, AI	RM
	, Arduino and Intel Galileo boards.	-			
UNIT - II			ture		
	Access Technologies: Physical and MAC layers, topology and				
	4g, 802.15.4e, 1901.2a, 802.11ah and Lora WAN, Network Laes and Constrained Networks, Optimizing IP for IoT: From 6L				
	Power and Lossy Networks, Application Transport Methods: Su				
	ion, Application Layer Protocols: CoAP and MQTT.	pci vi	SOI y	Com	101
UNIT - III	ion, rippheation Eager Protocols. Corn and mg 11.	Lec	ture	Hrs	
	elopment: Design Methodology, Embedded computing logic,				ler
	IoT system building blocks, Arduino, Board details, IDE program				
	Raspberry Pi with Python Programming.		8, -10	Брос)
UNIT - IV	The state of the s	Lec	ture	Hrs:	
Data Analytics a	nd Supporting Services: Structured Vs Unstructured Data and D				Vs
_	e of Machine Learning – No SQL Databases, Hadoop Ecosysten				
	ge Streaming Analytics and Network Analytics, Xively Cloud for				
Application Fram	ework, Django, AWS for IoT, System Management with NETCON	VF-Y	AN(3.	
UNIT - V		Lec	ture	Hrs:	
Case Studies/Ind	ustrial Applications: IoT applications in home, infrastructures, but	uildii	ngs, s	ecur	ity,
	appliances, other IoT electronic equipments. Use of Big Data and				
T	concepts. Sensors and sensor Node and interfacing using any	Emb	edde	d tar	get
	Pi / Intel Galileo/ARM Cortex/ Arduino).				
Textbooks:					
1. IoT Fundame	ntals: Networking Technologies, Protocols and Use Cases for In	terne	et of	Thin	gs,

Press, 2017.

David Hanes, Gonzalo Salgueiro, Patrick Grossetete, Rob Barton and Jerome Henry, Cisco



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COMMON COURSE STRUCTURE & SYLLABI

2. Internet of Things – A hands-on approach, ArshdeepBahga, Vijay Madisetti, Universities Press, 2015

Reference Books:

- 1. The Internet of Things Key applications and Protocols, Olivier Hersent, David Boswarthick, Omar Elloumi and Wiley, 2012 (for Unit 2).
- 2. "From Machine-to-Machine to the Internet of Things Introduction to a New Age of Intelligence", Jan Holler, VlasiosTsiatsis, Catherine Mulligan, Stamatis, Karnouskos, Stefan Avesand. David Boyle and Elsevier, 2014.
- 3. Architecting the Internet of Things, Dieter Uckelmann, Mark Harrison, Michahelles and Florian (Eds), Springer, 2011.



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

Course Code	VLSI SIGNAL PROCESSING	L	T	P	C
21D57204c		3	0	0	3
	Semester		I	I	
Course Objective	es:				
• To stu	dy the existing architectures suitable for VLSI.				
• To und	derstand the concepts of folding and unfolding algorithms and appl	icati	ons.		
• To des	ign new architectures suitable for VLSI.				
	plement fast convolution algorithms.				
	s (CO): Student will be able to				
	the existing architectures suitable for VLSI.				
-	stand the concepts of folding and unfolding algorithms and applica	tions	S.		
	n new architectures suitable for VLSI.	· CIOII	•		
_	ment fast convolution algorithms.				
UNIT - I	nent last convolution argorithms.	Lec	cture	Hrs	
	DSP: Typical DSP algorithms, DSP algorithms benefits, Repres				SP
	ning and Parallel Processing Introduction, Pipelining of FIR Digit				
	ining and Parallel Processing for Low Power Retiming Introduction				
	olving System of Inequalities, Retiming Techniques	<i>,</i> ,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	, DC1	min	711 5
UNIT - II	Tring bystem of inequalities, feetining feetiniques	Lec	cture	Hrs	
	Colding: Folding- Introduction, Folding Transform, Register				ion
	ster minimization in folded architectures, folding of Multirate sys				
	Algorithm for Unfolding, Properties of Unfolding, critical				
	plications of Unfolding.	I at	11, 01	nora	5
UNIT - III	phomions of chrotomy.	Lec	cture	Hrs	
	ture Design: Introduction, Systolic Array Design Methodolog				olic
	of Scheduling Vector, Matrix Multiplication and 2D Systoli				
	or Space Representations contain Delays.		iraj	2001	D,
UNIT - IV		Lec	cture	Hrs:	
	n: Introduction – Cook - Toom Algorithm – Winogard algo				ted
	clic Convolution – Design of Fast Convolution algorithm by Inspe			11014	ıca
UNIT - V			cture	Hrs	
	ign: Digital lattice filter structures, bit level arithmetic, archite				ant
	rical strength reduction, synchronous, wave and asynchronous pi				
	sumption, Power Analysis, Power Reduction techniques, Po	-			_
Approaches	amption, Tower That John, Tower Reduction techniques, To	J 11 CI	250	1111111	
Textbooks:					
	hi, VLSI Digital Signal Processing- System Design and Implement	atio	n, W	llev	
Inter Science,			, , , ,		
*	J. While House, T. Kailath ,VLSI and Modern Signal processing , l	Pren	tice H	Iall,	
1985.					
Reference Books				_	
1. Jose E. France,	Yannis Tsividis, Design of Analog – Digital VLSI Circuits for				
	ations and Signal Processing, Prentice Hall, 1994.				
2. Medisetti V. K	,VLSI Digital Signal Processing, IEEE Press (NY), 1995				



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

COMMON COURSE STRUCTURE & SYLLABI

Course Code	CMOS MIXED SIGNAL IC DESIGN LAB	L	T	P	C
21D57205		0	0	4	2
	Semester	II			

Course Objectives:

- To design and simulate op-amp for given specifications
- To design and simulate data converter for given specifications
- To design and simulate PLL and VCO for given specifications
- To understand the Significance of Pre-Layout Simulation and Post-Layout Simulation.

Course Outcomes (CO):

- Design and simulate op-amp for given specifications
- Design and simulate data converter for given specifications
- Design and simulate PLL and VCO for given specifications
- Understand the Significance of Pre-Layout Simulation and Post-Layout Simulation.

List of Experiments:

The students are required to design and implement the Circuit and Layout of the following Experiments using CMOS 130nm Technology.

Cycle 1:

- 1) Fully compensated op-amp with resistor and miller compensation
- 2) High speed comparator design
 - a. Two stage cross coupled clamped comparator
 - b. Strobed Flip-flop
- 3) Data converter

Cycle 2:

- 1) Switched capacitor circuits
 - a. Parasitic sensitive integrator
 - b. Parasitic insensitive integrator
- 2) Design of PLL
- 3) Design of VCO
- 4) Band gap reference circuit
- 5) Layouts of All the circuits Designed and Simulated

Software:

Mentor Graphics/ Cadence/ Tanner/Industry Equivalent Standard Software Tools

Hardware:

Personal Computer with necessary peripherals, configuration and operating System.

References:

- 1. David A johns, Ken Martin, Analog Integrated Circuit Design, Wiley, 2008.
- 2. R. Gregorian and G.C Ternes, Analog MOS Integrated Circuits for Signal Processing, Wiley,1986.
- 3. Roubik Gregorian, Introduction to CMOS OpAmp and Comparators, Wiley, 1999.
- 4. Alan Hastlings, The art of Analog Layout, Wiley, 2005.



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COMMON COURSE STRUCTURE & SYLLABI

Course Code	PHYSICAL DESIGN AUTOMATION LAB	L	T	P	C
21D57206		0	0	4	2
	Semester	II			

Course Objectives:

- To learn the implementation of different Physical Design Automation algorithms
- To implement different graph algorithms
- To implement different partitioning algorithms
- To implement different floor planning algorithms
- To implement different routing algorithms

Course Outcomes (CO):

- Learn the implementation of different Physical Design Automation algorithms
- Implement different graph algorithms
- Implement different partitioning algorithms
- Implement different floor planning algorithms
- Implement different routing algorithms

List of Experiments:

Cycle 1:

- 1) Graph algorithms
 - a) Graph search algorithms
 - i. Depth first search
 - ii. Breadth first search
 - b) Spanning tree algorithm
 - i. Kruskal"s algorithm
 - c) Shortest path algorithm
 - i. Dijkstra algorithm
 - ii. Floyd- Warshall algorithm
 - d) Steiner tree algorithm
- 2) Computational geometry algorithm
 - a) Line sweep method
 - b) Extended line sweep method

Cycle 2:

- 3) Partitioning algorithms
 - a) Group migration algorithms
 - I. Kernighan –Lin algorithm
 - II. Extensions of Kernighan-Lin algorithm
 - i) Fiduccias –Mattheyses algorithm
 - ii) Goldberg and Burstein algorithm
 - b) Simulated annealing and evolution algorithms
 - i. Simulated annealing algorithm
 - ii. Simulated evolution algorithm
 - III) Metric allocation method
- 4) Floor planning algorithms
 - i) Constraint based methods
 - ii) Integer programming based methods
 - iii) Rectangular dualization based methods
 - iv) Hierarchical tree based methods



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COMMON COURSE STRUCTURE & SYLLABI

- v) Simulated evolution algorithms
- vi) Time driven Floor planning algorithms
- 5) Routing algorithms
 - I) Two terminal algorithms
 - a) Maze routing algorithms
 - i)Lee"s algorithm
 - ii) Soukup"s algorithm
 - iii) Hadlock algorithm
 - b) Line-Probe algorithm
 - c) Shortest path based algorithm
 - II) Multi terminal algorithm
 - a) Stenier tree based algorithm
 - i) SMST algorithm
 - ii) Z-RST algorithm

Software required: C/C++ Programming Language /Relevant software **Text Books:**

- 1) Naveed Shervani, Algorithms for Physical Design Automation, 3rd Edition, Kluwer Academic, 1998.
- 2) Charles J Alpert, Dinesh P Mehta, Sachin S. Sapatnekar, Handbook of Algorithms for Physical Design Automation, CRC Press, 2008.



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

Course Code	BICMOS TECHNOLOGY AND APPLICATIONS	L	T	P	C
21D57301a		3	0	0	3
	Semester		II	I	
<u> </u>					
Course Objective					
	nonstrate in-depth knowledge in BiCMOS Technology.	_			_ ~
	lyze complex engineering problems critically for conducting res	earch	ın B	1CM	OS
Techn		D 1.	_		
	ve engineering problems with wide range of solutions in	Radio	o Fre	equer	ю
_	ated circuits. ize different digital circuits using BiCMOS Technology				
	s (CO): Student will be able to				
	astrate in-depth knowledge in BiCMOS Technology.	1.	: D	:CM	\sim c
Techn	te complex engineering problems critically for conducting reserved	arcii	III D	ICM	US
	engineering problems with wide range of solutions in Radio Fre	auan	ov In	agra	tad
circuit		quem	<i>y</i> 1111	icgra	ıcu
	e different digital circuits using BiCMOS Technology				
UNIT - I	s different digital effective using blefriob Teenhology	Lect	ure I	Irs:	
	s Technology: CMOS Process Technology, Bipolar Process Technology				ion
	olar Technologies, BiCMOS Technology, BiCMOS Design Rules		6), -	00144	
UNIT - II			ure I	Irs:	
	onsiderations: Design Considerations for MOSFET's, Design C				for
	rs, BiCMOS Device Design Considerations.				
	Scaling: MOS Device Scaling, Bipolar Device Scaling.				
UNIT - III		Lect	ure I	Irs:	
Device Modeling	: Modeling of the MOS Transistor: MOSFET Structure and	Opera	ition,	SPI	CE
	S Transistor, Analytical Model for Short-Channel MOS Devices.				
•	Bipolar Transistor: BJT Structure and Operation, Ebers-Mol	1 Mc	odel,	Bipo	olar
Models in SPICE					
UNIT - IV			ure I		
	Integrated Circuits: BiMOS Totem-Pole Inveter: DC Charact				
•	Dependence on the Device Parameters, BiCMOS Circuit Design, Contact PicMOS Cates	Comp	arıng	CM	OS
	erters Speed, BiCMOS Gates.	Last	T	Tuo.	
UNIT - V BiCMOS Digit	ol Cinquit Applications, Addams Multiplian Dandam		ure F		
	al Circuit Applications: Adders, Multiplier, Random Agic Arrays, BiCMOS Logic Cells, BiCMOS Gate Arrays.	Acces	SS IV	iemo	ıгу,
Textbooks:	gic Arrays, Dicwos Logic Cens, Dicwos Gate Arrays.				
	nbabi, AbdellatifBellaouar& Mohamed I. Elmasry "Digital Bio	CMO	S In	teora	teć
	pringer Science+ BusÎness Media, LLC.	CIVIO	5 III	icgra	icc
	, BICMOS Technology & Applications, Kluwer Academic Publis	hers.			
Reference Books					
	Samir S. Rofail, Wang-Ling Goh, CMOS/BiCMOS ULSI, Pearson	n Edu	catio	n.	
	Denis P. Galipeau, Analog BiCMOS Design: Practices & Pitfalls,				
•	ngen, Johan Huijsing, Compact Low-Voltage and High-Speed				OS
J. Kiaasjaii ut La	ingon, vonan rialising, compact bow voltage and riigh speed		~, —		



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

COMMON COURSE STRUCTURE & SYLLABI

Course Objectives: To understand basics of statistical modeling
Course Objectives: To understand basics of statistical modeling To analyze performance of CMOS circuits with respect to power, area and speed To acquire complete knowledge regarding the various algorithms used for optimization of power and area Course Outcomes (CO): Student will be able to Understand basics of statistical modeling Analyze performance of CMOS circuits with respect to power, area and speed Acquire complete knowledge regarding the various algorithms used for optimization of power and area UNIT - I Lecture Hrs: Statistical Modeling: Modeling sources of variations, Monte Carlo techniques, Process variation modeling-Pelgrom's model, Principle component based modeling, Quad tree based modeling, Performance modeling-Response surface methodology, delay modeling, interconnect delay models. UNIT - II Lecture Hrs: Statistical Performance, Power and Yield Analysis: Statistical timing analysis, parameter space techniques, Bayesian networks Leakage models, High level statistical analysis, Gate level statistical analysis, dynamic power, leakage power, temperature and power supply variations, High level yield estimation and gate level yield estimation. UNIT - III Lecture Hrs: Convex Optimization: Convex sets, convex functions, geometric programming, prode-off and sensitivity analysis, Generalized geometric programming, geometric programming applied to digital circuit gate sizing, Floorplanning, wiresizing, Approximation andfitting-Monomial fitting, Maxmonomial fitting, Polynomial fitting. UNIT - IV Lecture Hrs: Genetic Algorithm: Introduction, GA Technology-Steady State Algorithm-Tisess Scaling Inversion GA for VLSI Design, Layout and Test automation- partitioning-automatic placement, routing technology, mappingfor FPGA-Automatic testgeneration-Partitioning algorithm Taxonomy-Multi-way Partitioning Hybrid genetic-encoding-local improvement-WDFR Comparison of CAS-Standard cell placement GASP algorithm-unified algorithm. UNIT - V Lecture Hrs:
To understand basics of statistical modeling To analyze performance of CMOS circuits with respect to power, area and speed To acquire complete knowledge regarding the various algorithms used for optimization of power and area Course Outcomes (CO): Student will be able to Understand basics of statistical modeling Analyze performance of CMOS circuits with respect to power, area and speed Acquire complete knowledge regarding the various algorithms used for optimization of power and area UNIT - I Lecture Hrs: Statistical Modeling: Modeling sources of variations, Monte Carlo techniques, Process variation modeling-Pelgrom's model, Principle component based modeling, Quad tree based modeling, Performance modeling-Response surface methodology, delay modeling, interconnect delay models. UNIT - II Lecture Hrs: Statistical Performance, Power and Yield Analysis: Statistical timing analysis, parameter space techniques, Bayesian networks Leakage models, High level statistical analysis, Gate level statistical analysis, dynamic power, leakage power, temperature and power supply variations, High level yield estimation and gate level yield estimation. UNIT - III Lecture Hrs: Convex Optimization: Convex sets, convex functions, geometric programming applied to digital circuit gate sizing, Floorplanning, wiresizing, Approximation andfitting-Monomial fitting, Maxmonomial fitting, Polynomial fitting. UNIT - IV Lecture Hrs: Genetic Algorithm: Introduction, GA Technology-Steady State Algorithm-Fitness Scaling-Inversion GA for VLSI Design, Layout and Test automation- partitioning-automatic placement, routing technology, mappingfor FPGA-Automatic testgeneration-Partitioning algorithm Taxonomy-Multi-way Partitioning Hybrid genetic-encoding-local improvement-WDFR Comparison of CAS-Standard cell placement GASP algorithm-unified algorithm. UNIT - V Lecture Hrs:
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GA Routing Proceduresand Power Estimation: Global routing-FPGA technology mapping-
circuit generation-test generation in a GA frame work-test generation procedures, Power estimation-application of GA Standard cellplacement – GA for ATG-problem encoding-fitness function-GA
application of GA Standard cellplacement – GAfor ATG-problem encoding-fitness function-GA Vs Conventional algorithm.
Textbooks:
1.Statistical Analysis and Optimization for VLSI: Timing and Power –Ashish Srivastava,
DennisSylvester, David Blaauw, Springer, 2005. 2. Genetic Algorithm for VLSI Design, Layout and Test Automation -PinakiMazumder,

1. Convex Optimization- Stephen Boyd, Lieven Vandenberghe, Cambridge University Press, 2004

Reference Books:



Reference Books:

JAWAHARLAL NEHRU TECHNOLOGICAL UNIVERSITY ANANTAPUR (Established by Govt. of A.P., ACT No.30 of 2008) ANANTHAPURAMU – 515 002 (A.P) INDIA

M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

Course Code	SoC ARCHITECTURE	L	T	P	С
21D06203a		3	0	0	3
	Semester	J	II	Ī	
Course Object	ives:				
To und	erstand the basics related to SoC architecture and different approach	hes re	lated	to S	oC
Design	2.2				
To sele	ct an appropriate robust processor for SoC Design				
	ct an appropriate memory for SoC Design.				
	ize real time case studies				
Course Outcom	nes (CO): Student will be able to				
	tand the basics related to SoC architecture and different approach	es re	lated	to S	oC
Design	**				
_	an appropriated robust processor for SoC Design				
	an appropriate memory for SoC Design.				
	real time case studies				
UNIT - I		Lect	ure F	Irs:	
	the System Approach: System Architecture, Components of the system	tem,	Hard	ware	
	rocessor Architectures, Memory & Addressing. System level interc				
	SOC Design, System Architecture and Complexity.				
UNIT - II		Lect	ure F	Irs:	
Processors: Intr	oduction, Processor Selection for SOC, Basic concepts in Processor	r Ar	chited	ture,	,
	s in Processor Microarchitecture, Basic elements in Instruction han				
minimizing Pi	peline Delays, Branches, More Robust Processors, Vector Pro	cesso	rs ar	ıd	
Vector Instru	ction extensions, VLIW Processors, Superscalar Processors				
UNIT - III			ure F	Irs:	
	for SOC: Overview: SOC external memory, SOC Internal Memory				
	nd Cache memory, Cache Organization, Cache data, Write Policies			s for	
	ent at miss time, Other Types of Cache, Split – I, and D – Caches, I		level		
	Memory System, Models of Simple Processor – memory interaction				
UNIT - IV			ure F	Irs:	
	ustomization and Configurability: Interconnect Architectures, Bus: I			_	
	SOC Standard Buses, Analytic Bus Models, Using the Bus model,	Effe	cts of	Bus	
	d contention time.	ъ	c.	1	1
	ization: An overview, Customizing Instruction Processor,				
	Mapping design onto Reconfigurable devices, Instance-				
reconfigurable	Soft Processor, Reconfiguration - overhead analysis and trade	-011	anary	SIS	ЭП
UNIT - V	r aranensin.	Locat	ure F	Irci	
	dies / Case Studies: SOC Design approach; AES-algorithms, Design				
	ssion–JPEG compression.	anu	cvaiu	auoi	1,
Textbooks:	obion of DO compression.				
	ystem Design System-on-Chip - Michael J. Flynn and Wayne Luk.	Wie	ly In	dia F	vt
Ltd.	Joseph Dystein on Chip Michael J. Hymr and Wayne Dak	, ,,,,	., .,	ara 1	, t.
	em on Chip Architecture – Steve Furber, 2ndEdition, 2000,	Add	ison	Wes	lev
Professional	-				- 5



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

- 1. Design of System on a Chip: Devices and Components Ricardo Reis, 1st Ed., 2004, Springer 2.Co-Verification of Hardware and Software for ARM System on Chip Design (EmbeddedTechnology) Jason Andrews Newnes, BK and CDROM.
- 3.System on Chip Verification Methodologies and Techniques –PrakashRashinkar, PeterPaterson and Leena Singh L, 2001, Kluwer Academic Publishers



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

COMMON COURSE STRUCTURE & SYLLABI

AUDIT COURSE-I



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

Course Code	ENGLISH FOR RESEARCH PAPER WRITING	L	T	P	C
21DAC101a		2	0	0	0
	Semester			I	
Course Objectiv	es: This course will enable students:				
Understa	nd the essentials of writing skills and their level of readability				
• Learn ab	out what to write in each section				
	ualitative presentation with linguistic accuracy				
Course Outcome	es (CO): Student will be able to				
 Understa 	nd the significance of writing skills and the level of readability				
 Analyze 	and write title, abstract, different sections in research paper				
Develop	the skills needed while writing a research paper				
UNIT - I	0 11	ectur	e Hrs	:10	
10verview of a l	Research Paper- Planning and Preparation- Word Order- Useful 1	Phras	es - I	Break	ing
up Long Sentence	es-Structuring Paragraphs and Sentences-Being Concise and Rem	oving	Red	undaı	ncy
-Avoiding Ambig	guity				
UNIT - II			e Hrs		
	nents of a Research Paper- Abstracts- Building Hypothesis-R			oblei	n -
Highlight Finding	gs- Hedging and Criticizing, Paraphrasing and Plagiarism, Cauteri	zatio	n		
UNIT - III	I	ectur	e Hrs	:10	
	ew of the Literature - Methodology - Analysis of the Data-Find	ings	- Dis	cussi	on-
Conclusions-Rec	ommendations.				
UNIT - IV		Le	cture	Hrs:	
	for writing a Title, Abstract, and Introduction	1			
UNIT - V		Le	cture	Hrs:9	
Appropriate lang	Lage to formulate Methodology, incorporate Results, put forth Ar	gume	ents a	nd dı	aw
Conclusions					
Suggested Read	ng				
1. Goldbort	R (2006) Writing for Science, Yale University Press (available or	Goo	gle E	Books)
	urriculum of Engineering & Technology PG Courses [Volume-I]		_		
	006) How to Write and Publish a Scientific Paper, Cambridge Un			ess	
	N (1998), Handbook of Writing for the Mathematical Sciences, S	IAM			
Highman					
	Vallwork, English for Writing Research Papers, Springer New Yo	rk Do	ordre	cht	
Heidelbe	rg London, 2011				



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

COMMON COURSE STRUCTURE & SYLLABI

Course Code	DIG A COURT A CANA CONTINUE	L	T	P	С
21DAC101b	DISASTER MANAGEMENT	2	0	0	0
	Semester]	[

Course Objectives: This course will enable students:

- Learn to demonstrate critical understanding of key concepts in disaster risk reduction and humanitarian response.
- Critically evaluatedisasterriskreduction and humanitarian response policy and practice from Multiple perspectives.
- Developanunderstandingofstandardsofhumanitarianresponseandpracticalrelevanceinspecific types of disasters and conflict situations
- Criticallyunderstandthestrengthsandweaknessesofdisastermanagementapproaches, planning and programming in different countries, particularly their home country or the countries they work in

UNIT - I

Introduction:

Disaster:Definition,FactorsandSignificance;DifferenceBetweenHazardandDisaster;Naturaland Manmade Disasters: Difference, Nature, Types and Magnitude.

Disaster Prone Areas in India:

Study of Seismic Zones; Areas Prone to Floods and Droughts, Landslides and Avalanches; Areas Prone to Cyclonic and Coastal Hazards with Special Reference to Tsunami; Post- Disaster Diseases and Epidemics

UNIT - II

Repercussions of Disasters and Hazards:

Economic Damage, Loss of Human and Animal Life, Destruction of Ecosystem. Natural Disasters: Earthquakes, Volcanisms, Cyclones, Tsunamis, Floods, Droughts and Famines, Landslides and Avalanches, Man-made disaster: Nuclear Reactor Meltdown, Industrial Accidents, Oil Slicks and Spills, Outbreaks of Disease and Epidemics, War and Conflicts.

UNIT - III

Disaster Preparedness and Management:

Preparedness: Monitoring of Phenomena Triggering ADisasteror Hazard; Evaluation of Risk: Application of Remote Sensing, Data from Meteorological and Other Agencies, Media Reports: Governmental and Community Preparedness.

UNIT - IV

Risk Assessment Disaster Risk:

Concept and Elements, Disaster Risk Reduction, Global and National Disaster Risk Situation. TechniquesofRiskAssessment,GlobalCo-OperationinRiskAssessmentand Warning, People's Participation in Risk Assessment. Strategies for Survival.

UNIT - V

Disaster Mitigation:

Meaning, Conceptand Strategies of Disaster Mitigation, Emerging Trends In Mitigation. Structural Mitigation and Non-Structural Mitigation, Programs of Disaster Mitigation in India.

Suggested Reading

- 1. R.Nishith, SinghAK, "Disaster Management in India: Perspectives, issues and strategies
- 2. "'New Royal book



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- Company..Sahni,PardeepEt.Al.(Eds.),"DisasterMitigationExperiencesAndReflections",PrenticeHa ll OfIndia, New Delhi.
- 3. GoelS.L.,DisasterAdministrationAndManagementTextAndCaseStudies",Deep&Deep Publication Pvt. Ltd., New Delhi



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Course Code	SANSKI	RITFOR TECHNICAL KNOWLEDGE	L	T	P	C		
21DAC101c			2	0	0	0		
		Semeste	r	Ï				
Course Objecti	ves: This cours	se will enable students:						
To get a	working know	vledge in illustrious Sanskrit, the scientific la	nguage in	n the wo	rld			
Learning of Sanskrit to improve brain functioning								
 Learnin 	gofSanskrittod	evelopthelogicinmathematics, science&others	ubjects e	nhancin	g the			
memory	power							
• The eng	ineering schola	ars equipped with Sanskrit will be able to exp	lore the	huge				
	edge from ancie							
Course Outcon	nes (CO): Stud	ent will be able to						
		anskrit language						
		ture about science &technology can be under	stood					
Being a	logical langua	ge will help to develop logic in students						
UNIT - I								
Alphabets in S	anskrit,							
UNIT - II								
Past/Present/Fut	ure Tense, Sim	ple Sentences						
UNIT - III								
Order, Introduct	ion of roots							
UNIT - IV								
Technical infor	mation about S	Sanskrit Literature						
UNIT - V								
Technical conc	epts of Engine	ering-Electrical, Mechanical, Architecture, M	athematic	es				
Suggested Read								
		ishwas, Sanskrit-Bharti Publication, New						
		rit" Prathama Deeksha- VempatiKutu	nbshastı	ri, Rash	triyaSa	nskrit		
Sansthanam, N								
3."India's Gloa	rious Scientifi	cTradition" Suresh Soni, Ocean books (F) Ltd.,N	ew Del	hi			



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COMMON COURSE STRUCTURE & SYLLABI

AUDIT COURSE-II



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

COMMON COURSE STRUCTURE & SYLLABI

21DAC201a		PEDAGOGY STUDIES	L	T	P	C
21DAC201a			2	0	0	0
		Semester]	Ī	
Carrage Objection	This					
Course Objectiv	ves: This cour	se will enable students:				
	0	ceon the review to pictoin form programme design a	ndpolic	y makii	ng	
	•	D, other agencies and researchers.				
<u>*</u> _		ce gaps to guide the development.				
	/	lent will be able to				
Students will be	able to unders	tand:				
• Whatped countries		icesarebeingusedbyteachersinformalandinforma	alclassr	ooms in	develo	ping
		on the effectiveness of these pedagogical practic	es, in v	vhat		
		that population of learners?	ou lumo	nd anid	nnaa	
		on(curriculumandpracticum)andtheschoolcurriculumandpracticum)andtheschoolcurriculumandpracticum)andtheschoolcurriculumandpracticum)andtheschoolcurriculumandpracticum)andtheschoolcurriculumandpracticum)andtheschoolcurriculumandpracticum)andtheschoolcurriculumandpracticum)andtheschoolcurriculumandpracticum)andtheschoolcurriculumandpracticum)andtheschoolcurriculumandpracticum)andtheschoolcurriculumandpracticum)andtheschoolcurriculumandpracticum	culullia	na gura	ance	
UNIT - I	s dest support					
4	T1	ogy: Aims and rationale, Policy back ground,				
	Theories view of metho	oflearning, Curriculum, Teachereducation. Corodology and Searching.				
questions. Over	view of metho	oflearning, Curriculum, Teachereducation. Corodology and Searching.	nceptua	lframew	ork,Res	search
questions. Over UNIT - II Thematic over	view of metho	oflearning, Curriculum, Teachereducation. Cor	nceptua	lframew	ork,Res	
questions. Over UNIT - II Thematic over	view of metho	oflearning, Curriculum, Teachereducation. Corodology and Searching. ogical practices are being used by teachers	nceptua	lframew	ork,Res	search
questions. Over UNIT - II Thematic over classrooms in d UNIT - III Evidence on the of included sturn guidance material evidence for eff	rview: Pedage eveloping courselfectivenessedies. How can ials best supported fective pedage	oflearning, Curriculum, Teachereducation. Corodology and Searching. ogical practices are being used by teachers	in for	rmal are:quality	assess	formal men to men and
questions. Over UNIT - II Thematic over classrooms in d UNIT - III Evidence on the of included sturn guidance material evidence for eff	rview: Pedage eveloping courselfectivenessedies. How can ials best supported fective pedage	oflearning, Curriculum, Teachereducation. Corodology and Searching. ogical practices are being used by teachers ntries. Curriculum, Teacher education. ofpedagogical practices, Methodology for the independent teacher education (curriculum and practicum) ort effective pedagogy? Theory of change. Strentogical practices. Pedagogic theory and pedago	in for	rmal are:quality	assess	formal men to men and

Suggested Reading

1. AckersJ, HardmanF(2001)ClassroominteractioninKenyanprimaryschools, Compare, 31 (2): 245-261.

Researchgapsandfuturedirections: Researchdesign, Contexts, Pedagogy, Teachereducation,

- 2. AgrawalM(2004)Curricularreforminschools:Theimportanceofevaluation,Journalof
- 3. Curriculum Studies, 36 (3): 361-379.

Curriculum and assessment, Dissemination and research impact.



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- 4. AkyeampongK(2003) Teacher training in Ghana does it count? Multi-site teachereducation research project (MUSTER) country report 1. London: DFID.
- 5. Akyeampong K, LussierK, PryorJ, Westbrook J (2013)Improving teaching and learning of basic maths and reading in Africa: Does teacherpreparation count?International Journal Educational Development, 33 (3): 272–282.
- 6. Alexander RJ(2001) Culture and pedagogy: International comparisons in primary education. Oxford and Boston: Blackwell.
 - Chavan M (2003)ReadIndia: A mass scale, rapid, 'learning to read'campaign.
- 7. www.pratham.org/images/resource%20working%20paper%202.pdf.



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Course Code	CIDD		L	T	P	C	
21DAC201b	51R	RESSMANAGEMENT BY YOGA	2	0	0	0	
		Semester		I	I		
Course Objecti	ves: This cours	e will enable students:					
 To achie 	eve overall heal	th of body and mind					
• To over	come stres						
Course Outcon	nes (CO): Stude	ent will be able to					
Develop	healthy mind i	in a healthy body thus improving social health	also				
_	efficiency	, , , ,					
UNIT - I							
Definitions of I	Eight parts of yo	og.(Ashtanga)					
UNIT - II							
Yam and Niyar	n.						
UNIT - III							
Do`sand Don't	'sin life.						
i) Ahinsa,satya	astheya,bramha,	acharyaand aparigrahaii)					
Shaucha, santos	h,tapa,swadhya	y,ishwarpranidhan					
UNIT - IV							
Asan and Prana	ıyam						
UNIT - V							
i)Variousyogpo	sesand theirber	nefitsformind &body					
ii)Regularizatio	onofbreathingte	chniques and its effects-Types of pranayam					
Suggested Read							
	1. 'Yogic Asanas forGroupTarining-Part-I': Janardan SwamiYogabhyasiMandal, Nagpur						
		e Internal Nature" by Swami Vivekanano	la, Adv	aita			
Ashrama (Public	cation Departme	ent), Kolkata					



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Course Code	PERSONALI	TY DEVELOPMENT TH	ROUGHLIFE	L	T	P	C
21DAC201c		NLIGHTENMENTSKILL		2	0	0	0
			Semester		I	I	
Course Objecti	ves: This course	will enable students:					
• To learn	to achieve the hi	ghest goal happily					
	_	stable mind, pleasing perso	nality and deterr	nination	l		
	ten wisdom in stu						
	nes (CO): Studen						
		d-Geetawillhelpthestudentii	ndevelopinghispe	ersonalit	yand ac	chieve	
_	est goal in life						
_		ied Geetawilllead the nation		_		perity	
	f Neetishatakam v	will help in developing versa	tile personality	of stude	nts		
UNIT - I							
	_	nent of personality					
	20,21,22(wisdom)						
	31,32(pride &her	oism)					
	28,63,65(virtue)		·				
UNIT - II							
Neetisatakam-	Holistic developn	nent of personality					
Verses-52,	53,59(dont's)						
Verses-71,	73,75,78(do's)						
UNIT - III							
Approach to da	y to day work and	d duties.					
ShrimadBh	agwadGeeta:Cha	pter2-Verses41,47,48,					
Chapter3-V	Verses 13, 21, 27, 35	,Chapter6-Verses5,13,17,23	,35,				
Chapter 18-	Verses45,46,48.						
UNIT - IV							
Statements of b	asic knowledge.						
ShrimadBh	agwadGeeta:Cha	pter2-Verses 56,62,68					
Chapter12	-Verses 13, 14, 15,	16,17,18					
Personality	of Rolemodel. S	hrimad Bhagwad Geeta:					
UNIT - V		<u>-</u>					
Chapter2-V	erses 17,Chapter	3-Verses36,37,42,					
Chapter4-V	Verses 18, 38, 39						
Chapter 18-	- Verses37,38,63						
Suggested Read							
1."SrimadBhaga Kolkata	wadGita"bySwan	niSwarupanandaAdvaitaAsh	ram(Publication	Departr	nent),		
		iti-sringar-vairagya) by P.	Gopinath, Rasht	riyaSan	skrit		



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COMMON COURSE STRUCTURE & SYLLABI

OPEN ELECTIVE



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

COMMON COURSE STRUCTURE & SYLLABI

Course Code	INDUSTRIAL SAFETY	L	T	P	C
21DOE301b		3	0	0	3
Semester				III	

Course Objectives:

- To know about Industrial safety programs and toxicology, Industrial laws, regulations and source models
- To understand about fire and explosion, preventive methods, relief and its sizing methods
- To analyse industrial hazards and its risk assessment.

Course Outcomes (CO): Student will be able to

- To list out important legislations related to health, Safety and Environment.
- To list out requirements mentioned in factories act for the prevention of accidents.
- To understand the health and welfare provisions given in factories act.

UNIT - I Lecture Hrs:

Industrial safety: Accident, causes, types, results and control, mechanical and electrical hazards, types, causes and preventive steps/procedure, describe salient points of factories act 1948 for health and safety, wash rooms, drinking water layouts, light, cleanliness, fire, guarding, pressure vessels, etc, Safety color codes. Fire prevention and firefighting, equipment and methods.

UNIT - II Lecture Hrs:

Fundamentals of maintenance engineering: Definition and aim of maintenance engineering, Primary and secondary functions and responsibility of maintenance department, Types of maintenance, Types and applications of tools used for maintenance, Maintenance cost & its relation with replacement economy, Service life of equipment.

UNIT - III Lecture Hrs:

Wear and Corrosion and their prevention: Wear-types, causes, effects, wear reduction methods, lubricants-types and applications, Lubrication methods, general sketch, working andapplications, i. Screw down grease cup, ii. Pressure grease gun, iii. Splash lubrication, iv. Gravity lubrication, v. Wick feed lubrication vi. Side feed lubrication, vii. Ring lubrication, Definition, principle and factors affecting the corrosion. Types of corrosion, corrosion prevention methods.

UNIT - IV Lecture Hrs:

Fault tracing: Fault tracing-concept and importance, decision treeconcept, need and applications, sequence of fault finding activities, show as decision tree, draw decision tree for problems in machine tools, hydraulic, pneumatic,automotive, thermal and electrical equipment's like, I. Any one machine tool, ii. Pump iii. Air compressor, iv. Internal combustion engine, v. Boiler, vi. Electrical motors, Types of faults in machine tools and their general causes.

UNIT - V Lecture Hrs:

Periodic and preventive maintenance: Periodic inspection-concept and need, degreasing, cleaning and repairing schemes, overhauling of mechanical components, overhauling of electrical motor, common troubles and remedies of electric motor, repair complexities and its use, definition, need, steps and advantages of preventive maintenance. Steps/procedure for periodic and preventive maintenance of: I. Machine tools, ii. Pumps, iii. Air compressors, iv. Diesel generating (DG) sets, Program and schedule of preventive maintenance of mechanical and electrical equipment, advantages of preventive maintenance. Repair cycle concept and importance

Textbooks:

- 1. Maintenance Engineering Handbook, Higgins & Morrow, Da Information Services.
- 2. Maintenance Engineering, H. P. Garg, S. Chand and Company.

Reference Books:

- 1. Pump-hydraulic Compressors, Audels, Mcgrew Hill Publication.
- 2. Foundation Engineering Handbook, Winterkorn, Hans, Chapman & Hall London.



M.TECH. IN VLSI/VLSI DESIGN/VLSI YSTEM DESIGN

Course Code	BUSINESS ANALYTICS	L	T	P	C
21DOE301c		3	0	0	3
	Semester			III	
Course Objectives					
	bjective of this course is to give the student a comprehensive under alytics methods.	rstar	nding	of	
Course Outcomes	(CO): Student will be able to				
	ill demonstrate knowledge of data analytics.				
	ill demonstrate the ability of think critically in making decisions basep analytics.	ised	on		
	ill demonstrate the ability to use technical skills in predicative and				
	e modeling to support business decision-making.				
Students w	ill demonstrate the ability to translate data into clear, actionable ins	ight	s.		
UNIT - I		Le	cture		
	Overview of Business Analysis, Overview of Requirements, R	lole	of th	ne Bu	siness
Analyst.					
Stakeholders: the p	roject team, management, and the front line, Handling Stakeholder	Cor	flicts	S.	
UNIT - II			cture		
	ms Development Life Cycles, Project Life Cycles, Product Life	Cycl	es, F	Require	ement
Life Cycles.					
UNIT - III		Le	cture	Hrs:	
	nents: Overview of Requirements, Attributes of Good Requ				
	uirement Sources, Gathering Requirements from Stakeholders, Co				
	orming Requirements: Stakeholder Needs Analysis, Decor				
Additive/Subtractiv	ve Analysis, Gap Analysis, Notations (UML & BPMN), Flow	/cha	rts, S	Swim	Lane
	Relationship Diagrams, State-Transition Diagrams, Data Flow	Diag	grams	, Use	Case
Modeling, Business UNIT - IV	s Process Modeling	Ιa	otumo.	I Ima.	
	ments: Presenting Requirements, Socializing Requirements and			Hrs:	onco
	ements. Managing Requirements Assets: Change Control, Requirements				tance,
Thornizing Require	ments. Managing Requirements Assets. Change Control, Require	110110	.5 10	<i>J</i> 13	
UNIT - V		Le	cture	Hrs:	
Recent Trands in	: Embedded and colleborative business intelligence, Visual of	lata	reco	very,	Data
Storytelling and Da					
Textbooks:					
1. Business Analys	is by James Cadle et al.				
	nent: The Managerial Process by Erik Larson and, Clifford Gray				
Reference Books:					
Business ar	nalytics Principles, Concepts, and Applications by Marc J. Schnied	erjaı	ıs, D	ara G.	
	ns, Christopher M. Starkey, Pearson FT Press.				
2. Business A	nalytics by James Evans, persons Education.				



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COMMON COURSE STRUCTURE & SYLLABI

Course Code	WASTE TO ENERGY	L	Т	P	С
21DOE301e	WASIE TO EXERCI	3	0	0	3
ZIDOESUIC	Semester	III		U	
	Semester				
Course Objective	es:				
· ·	and explain energy from waste, classification and devices to	cor	ivert	wast	te to
energy.	1 23				
 To impart 	knowledge on biomass pyrolysis, gasification, combustion and co	nver	sion	proce	ess.
•	te on biogas properties ,bio energy system, biomass resources and			•	
	ass energy programme in India.				
	s (CO): Student will be able to				
To know a	about overview of Energy to waste and classification of waste.				
	e knowledge on bio mass pyrolysis, gasification, combustion and	conv	ersic	n pro	ocess
in detail.					
	knowledge on properties of biogas, biomass resources and programme and p	ramr	nes t	o coi	nvert
	nergy in India.				
UNIT - I				Hrs:	
	nergy from Waste: Classification of waste as fuel - Agro base	ed, I	Fores	t res	idue,
	MSW – Conversion devices – Incinerators, gasifiers, digestors			**	1.0
UNIT - II	a Demolysis Temps alow fact. Manufacture of chancel			Hrs:	
	s: Pyrolysis – Types, slow fast – Manufacture of charcoal – Manufacture of pyrolytic oils and gases, yields and applications.	Met	noas	- Y1	leids
UNIT - III		Lec	cture	Hrs:	12
	tion: Gasifiers - Fixed bed system - Downdraft and updraft ga				
	esign, construction and operation - Gasifier burner arrangement for				
	ne arrangement and electrical power - Equilibrium and kin	netic	cons	sidera	ıtion
in gasifier operation	on	-			
UNIT - IV				Hrs:	
	tion: Biomass stoves – Improved chullahs, types, some exotic c	_			
	es, inclined grate combustors, Fluidized bed combustors, Design tion of all the above biomass combustors.	, coi	nstru	ction	and
UNIT - V	tion of all the above biomass combustors.	Lec	rture	Hrs:	10
	es of biogas (Calorific value and composition) - Biogas plan				
	gy system - Design and constructional features - Biomass re			~.	
classification -	8, 2,2 12-8 1112 13-12-13-13-13-13-13-13-13-13-13-13-13-13-13-				
	ion processes - Thermo chemical conversion - Direct comb	ustic	on -	bior	nass
	lysis and liquefaction - biochemical conversion - anaerobic dig				
	Applications - Alcohol production from biomass - Bio die	esel	proc	luctio	n -
	energy conversion - Biomass energy programme in India.				
Textbooks:					
	ventional Energy, Desai, Ashok V., Wiley Eastern Ltd., 2018		. ~	~ -	
2. Biogas To 2017	echnology - A Practical Hand Book - Khandelwal, K. C. and M.	lahd	1, S.	S., T	MH,
Reference Books					

2. Biomass Conversion and Technology, C. Y. WereKo-Brobby and E. B. Hagan, John Wiley

1. Food, Feed and Fuel from Biomass, Challal, D. S., IBH Publishing Co. Pvt. Ltd., 1991.



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COMMON COURSE STRUCTURE & SYLLABI

& Sons, 1996

Online Learning Resources:

https://nptel.ac.in/noc/courses/noc19/SEM1/noc19-ch13/https://www.youtube.com/watch?v=x2KmjbCvKTk